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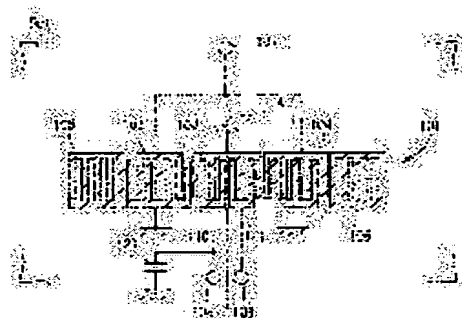
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(54) SURFACE ACOUSTIC WAVE DEVICE AND COMMUNICATION APPARATUS

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a surface acoustic wave device improved with respect to the phase balance and a communication apparatus using the same.

SOLUTION: A longitudinal coupled resonator type surface acoustic wave filter 101 having three IDTs formed in the propagating direction of surface acoustic waves is provided on a piezoelectric board 501. The IDT 103 located at the mid position among the three IDTs of the longitudinal coupled resonator type surface acoustic wave filter 101 is divided into two divisions approximately symmetrically to the propagating direction of the surface acoustic wave, and they are connected to balanced signal terminals 108, 109. The right and left IDTs 102, 104 having inverted polarities are connected to an unbalanced signal terminal 107 to obtain a balance-unbalance converting function. A reactance component 120 formed inside or outside a package is connected to either the balanced signal terminal 108 or 109 on the piezoelectric board 501.



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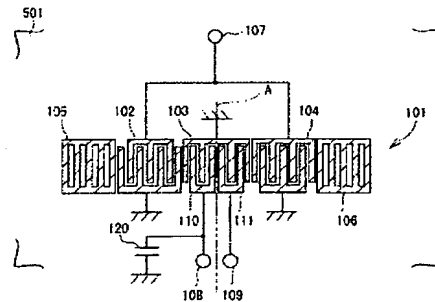
(54) 【発明の名称】 弾性表面波装置、通信装置

(57) 【要約】

【課題】 位相平衡が改善された弾性表面波装置及びそれを用いた通信装置を提供する。

【解決手段】 圧電基板 501 上に弾性表面波の伝搬方向に沿って形成された 3 つの IDT を有する縦結合共振子型弾性表面波フィルタ 101 を設ける。縦結合共振子型弾性表面波フィルタ 101 の 3 つの IDT のうち中央に位置する IDT 103 を弾性表面波の伝搬方向に略対称に 2 分割してそれぞれを平衡信号端子 108、109 に接続する。極性を反転させた左右の各 IDT 102、104 を不平衡信号端子 107 に接続することで平衡-不平衡変換機能を持たせる。平衡信号端子 108、109 の何れかに対して、圧電基板 501 上に、パッケージ内部に、又はパッケージ内部の外に、形成したリアクタンス成分 120 を接続する。

【選択図】 図 1



【特許請求の範囲】

【請求項 1】

圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡-不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指が浮き電極若しくは接地された電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子の方が相対的に寄生容量が大きくなるように、引き回し配線が非対称に形成されていることを特徴とする、弾性表面波装置。

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【請求項 2】

圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡-不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指がシグナル電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指がシグナル電極であるくし型電極部に近い側に位置する平衡信号端子の方が相対的に寄生容量が大きくなるように、引き回し配線が非対称に形成されていることを特徴とする、弾性表面波装置。

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【請求項 3】

前記圧電基板が、フリップチップボンディングでパッケージに搭載されており、前記非対称にした引き回し配線が該パッケージに形成されていることを特徴とする、請求項1又は2に記載の弾性表面波装置。

【請求項 4】

前記中央に位置するくし型電極部の中心に、弾性表面波の伝搬方向に対し垂直方向に設けた仮想軸に対して、前記非対称な引き回し配線以外の前記圧電基板上及びパッケージの引き回し配線が略対称に形成されていることを特徴とする、請求項1ないし3の何れか1項に記載の弾性表面波装置。

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【請求項 5】

圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡-不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指が浮き電極若しくは接地された電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線が付加されていることを特徴とする、弾性表面波装置。

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前記中央に位置するくし型電極部の最外電極指が浮き電極若しくは接地された電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線が付加されていることを特徴とする、弾性表面波装置。

【請求項 6】

圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電

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極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡-不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、

前記中央に位置するくし型電極部の最外電極指がシグナル電極であり、

前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指がシグナル電極であるくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線が付加されていることを特徴とする、弾性表面波装置。

【請求項7】

前記圧電基板が、フリップチップボンディングでパッケージに搭載されており、前記リアクタンス成分又は遅延線が該パッケージに形成されていることを特徴とする、請求項5又は6に記載の弾性表面波装置。

【請求項8】

前記中央に位置するくし型電極部の中心に、弾性表面波の伝搬方向に垂直に設けた仮想軸に対して、前記リアクタンス成分又は遅延線以外の前記圧電基板上及びパッケージ上の引き回し配線が略対称に設定されていることを特徴とする、請求項5ないし7の何れか1項に記載の弾性表面波装置。

【請求項9】

前記リアクタンス成分が、キャパシタンス成分であり、前記平衡信号端子とアース電位との間に並列に接続されていることを特徴とする、請求項5ないし8の何れか1項に記載の弾性表面波装置。

【請求項10】

前記リアクタンス成分が、インダクタンス成分であり、前記平衡信号端子に直列に接続されていることを特徴とする、請求項5ないし8の何れか1項に記載の弾性表面波装置。

【請求項11】

前記弾性表面波フィルタに対して、直列及び／又は並列に弾性表面波共振子が付加されていることを特徴とする、請求項1ないし10の何れか1項に記載の弾性表面波装置。

【請求項12】

前記弾性表面波フィルタが、複数、互いにカスケード接続されていることを特徴とする、請求項1ないし11の何れか1項に記載の弾性表面波装置。

【請求項13】

前記カスケード接続した弾性表面波フィルタの総電極指本数が偶数本であることを特徴とする、請求項12に記載の弾性表面波装置。

【請求項14】

前記の互いにカスケード接続された各弾性表面波フィルタのそれぞれの両端に位置するくし型電極部が、シグナルラインを介してそれぞれ接続され、且つ該各シグナルラインを伝送する信号の位相が互いに約180度異なるように設定されていることを特徴とする、請求項12又は13に記載の弾性表面波装置。

【請求項15】

前記弾性表面波フィルタのうち、互いに隣り合っているくし型電極部の少なくとも一方のくし型電極部における隣接部付近の電極指が重み付けされていることを特徴とする、請求項1ないし14の何れか1項に記載の弾性表面波装置。

【請求項16】

前記重み付けが直列重み付けであることを特徴とする、請求項15に記載の弾性表面波装置。

【請求項17】

前記圧電基板が、フリップチップボンディングでパッケージに搭載されており該パッケージの外部端子は、1つの不平衡信号端子、2つの平衡信号端子、3つのアース端子の6つであり、6つの端子が、前記弾性表面波フィルタの中央に位置するくし型電極部の中心に

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弾性表面波の伝搬方向に対し垂直方向に設けた仮想軸に対して、略対称に配置されていることを特徴とする、請求項1ないし16の何れか1項に記載の弾性表面波装置。

【請求項18】

前記圧電基板が、フリップチップボンディングでパッケージに搭載されており該パッケージの外部端子は、1つの不平衡信号端子、2つの平衡信号端子、2つのアース端子の5つであり、5つの端子が、前記弾性表面波フィルタの中央に位置するくし型電極部の中心に弾性表面波の伝搬方向に対し垂直方向に設けた仮想軸に対して、略対称に配置されていることを特徴とする、請求項1ないし16の何れか1項に記載の弾性表面波装置。

【請求項19】

請求項1ないし18の何れか1項に記載の弾性表面波装置を有していることを特徴とする 10
、通信装置。

【発明の詳細な説明】

【0001】

【発明の属する技術分野】

本発明は、平衡－不平衡変換機能を有する弾性表面波フィルタを備えた弾性表面波装置に関するものである。

【0002】

【従来の技術】

近年の携帯電話機（通信装置）の小型化、軽量化に対する技術的進歩は目覚ましいものがある。これを実現するための手段として、各構成部品の削減、小型化はもとより、複数の機能 20
を複合した部品の開発も進んできた。

【0003】

このような状況を背景に、携帯電話機のRF段に使用する弾性表面波装置に平衡－不平衡変換機能、いわゆるバランの機能を持たせたものも近年盛んに研究され、GSM（Global System for Mobile communications）などを中心に使用されるようになってきた。

【0004】

このような平衡－不平衡変換機能を持たせた弾性表面波装置に関する特許も、いくつか出願されている。図3に、特開平11-97966号公報に開示されている、不平衡信号端子側のインピーダンスが50Ω、平衡信号端子側のインピーダンスが200Ωに設定された平衡－不平衡変換機能を持たせた弾性表面波装置を示す。 30

【0005】

図3の構成は、くし型電極部（Inter-Digital Transducer、以下、IDTという）を、3つ、弾性表面波の伝搬方向に沿って有する縦結合共振子型弾性表面波フィルタ301において、中央に位置するIDT303を弾性表面波の伝搬方向に略対称に2分割してそれぞれを平衡信号端子308、309に接続し、極性を反転させた左右の各IDT302、304を不平衡信号端子307に接続している。これにより、上記構成においては、極性の反転によって平衡－不平衡変換機能を持たせることができ、さらに平衡信号端子側のインピーダンスは、IDT303の2分割により、不平衡信号端子側のインピーダンスの約4倍とすることができる。 40

【0006】

平衡－不平衡変換機能を有するフィルタでは、不平衡信号端子と平衡信号端子のそれぞれの端子との間の通過帯域内での伝送特性において、振幅特性が等しく、かつ位相が180度反転していることが要求され、それぞれ振幅平衡度及び位相平衡度と呼んでいる。

【0007】

振幅平衡度及び位相平衡度とは、前記平衡－不平衡変換機能を有するフィルタ装置を3ポートのデバイスと考え、例えば不平衡入力端子をポート1、平衡出力端子のそれぞれをポート2、ポート3としたときの、 $\text{振幅平衡度} = |A|$ 、 $A = |20 \log(S_{21})| - |20 \log(S_{31})|$ 、 $\text{位相平衡度} = |B - 180|$ 、 $B = |\angle S_{21} - \angle S_{31}|$ で定義する。このような平衡度は、理想的には弾性表面波フィルタの通過帯域内で振幅平 50

衡度が0 dB、位相平衡度は0度とされる。

【0008】

【発明が解決しようとする課題】

しかしながら、図3に示す従来の構成においては、平衡度が悪いという問題があった。その理由は、IDT303と隣り合う電極指の極性がIDT302とIDT304とで互いに異なっており（図3の310と311）、これにより、各平衡信号端子308、309のそれぞれに入る寄生容量、橋絡容量等が互いに異なるためである。

【0009】

本発明の目的は、図3の構成において上記の問題を解決し、平衡度を改善した平衡－不平衡変換機能を有し、かつ平衡信号端子のインピーダンスが不平衡信号端子のインピーダンスの約4倍である弾性表面波装置を提供することにある。

【0010】

【課題を解決するための手段】

本発明の弾性表面波装置は、以上の課題を解決するために、圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡－不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指が浮き電極若しくは接地された電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子の方が相対的に寄生容量が大きくなるように、引き回し配線が非対称に形成されていることを特徴としている。

【0011】

上記構成によれば、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子の方が相対的に寄生容量が大きくなるように、引き回し配線を非対称に形成することで、各平衡信号端子間の平衡度、特に位相平衡度を改善できる。

【0012】

本発明の他の弾性表面波装置は、以上の課題を解決するために、圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡－不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指がシグナル電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指がシグナル電極であるくし型電極部に近い側に位置する平衡信号端子の方が相対的に寄生容量が大きくなるように、引き回し配線が非対称に形成されていることを特徴としている。

【0013】

上記構成によれば、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指がシグナル電極であるくし型電極部に近い側に位置する平衡信号端子の方が相対的に寄生容量が大きくなるように、引き回し配線を非対称に形成することによって、各平衡信号端子間の平衡度、特に位相平衡度を改善できる。

【0014】

上記弾性表面波装置では、前記圧電基板が、フリップチップボンディングでパッケージに

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搭載されており、前記非対称にした引き回し配線が該パッケージに形成されていてもよい。

【0015】

上記弾性表面波装置においては、前記中央に位置するくし型電極部の中心に、弾性表面波の伝搬方向に対し垂直方向に設けた仮想軸に対して、前記非対称な引き回し配線以外の前記圧電基板上及びパッケージの引き回し配線が略対称に形成されていてもよい。

【0016】

本発明のさらに他の弾性表面波装置は、以上の課題を解決するために、圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡-不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指が浮き電極若しくは接地された電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線が付加されていることを特徴としている。

【0017】

上記構成によれば、中央に位置するくし型電極部に隣接する最外電極指が接地されているくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線を付加したことで、各平衡信号端子間の平衡度、特に位相平衡度を改善できる。

【0018】

本発明のさらに他の弾性表面波装置は、以上の課題を解決するために、圧電基板上に弾性表面波の伝搬方向に沿って形成された3つ以上の奇数個のくし型電極部を有し、前記奇数個のくし型電極部のうち中央に位置するくし型電極部の一方のくし型電極を弾性表面波の伝搬方向に2分割してそれぞれが平衡信号端子に接続され、該中央に位置するくし型電極部に隣接する2つのくし型電極部は互いに反転した構造を有すると共に不平衡信号端子に接続されている平衡-不平衡変換機能を有する縦結合共振子型の弾性表面波フィルタを備えた弾性表面波装置において、前記中央に位置するくし型電極部の最外電極指がシグナル電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指がシグナル電極であるくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線が付加されていることを特徴としている。

【0019】

上記構成によれば、中央に位置するくし型電極部の最外電極指がシグナル電極であり、前記中央に位置するくし型電極部に隣接する2つのくし型電極部のうち、前記中央に位置するくし型電極部に隣接する最外電極指がシグナル電極であるくし型電極部に近い側に位置する平衡信号端子にリアクタンス成分又は遅延線を付加したことによって、各平衡信号端子間の平衡度、特に位相平衡度を改善できる。

【0020】

上記弾性表面波装置では、前記圧電基板が、フリップチップボンディングでパッケージに搭載されており、前記リアクタンス成分又は遅延線が該パッケージに形成されていてもよい。

【0021】

上記弾性表面波装置においては、前記中央に位置するくし型電極部の中心に、弾性表面波の伝搬方向に垂直に設けた仮想軸に対して、前記リアクタンス成分又は遅延線以外の前記圧電基板上及びパッケージ上の引き回し配線が略対称に設定されていてもよい。

【0022】

上記弾性表面波装置では、前記リアクタンス成分が、キャパシタンス成分であり、前記平

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衡信号端子とアース電位との間に並列に接続されていてもよい。上記弾性表面波装置においては、前記リアクタンス成分が、インダクタンス成分であり、前記平衡信号端子に直列に接続されていてもよい。

【0023】

上記弾性表面波装置では、前記弾性表面波フィルタに対して、直列及び／又は並列に弾性表面波共振子が付加されていてもよい。上記弾性表面波装置においては、前記弾性表面波フィルタが、複数互いにカスケード接続されていてもよい。上記弾性表面波装置では、前記カスケード接続した弾性表面波フィルタの総電極指本数が偶数本であることが好ましい。

【0024】

上記弾性表面波装置においては、前記の互いにカスケード接続された各弾性表面波フィルタのそれぞれの両端に位置するくし型電極部が、シグナルラインを介してそれぞれ接続され、且つ該各シグナルラインを伝送する信号の位相が互いに約180度異なるように設定されていることが望ましい。

【0025】

上記弾性表面波装置では、前記弾性表面波フィルタのうち、互いに隣り合っているくし型電極部の少なくとも一方のくし型電極部における隣接部付近の電極指が重み付けされていてもよい。上記弾性表面波装置においては、前記重み付けが直列重み付けであってもよい。

【0026】

上記弾性表面波装置においては、前記圧電基板が、フリップチップボンディングでパッケージに搭載されており該パッケージの外部端子は、1つの不平衡信号端子、2つの平衡信号端子、3つのアース端子の6つであり、6つの端子が、前記弾性表面波フィルタの中央に位置するくし型電極部の中心に弾性表面波の伝搬方向に対し垂直方向に設けた仮想軸に対して略対称に配置されていてもよい。

【0027】

上記弾性表面波装置では、前記圧電基板が、フリップチップボンディングでパッケージに搭載されており該パッケージの外部端子は、1つの不平衡信号端子、2つの平衡信号端子、2つのアース端子の5つであり、5つの端子が、前記弾性表面波フィルタの中央に位置するくし型電極部の中心に弾性表面波の伝搬方向に対し垂直方向に設けた仮想軸に対して、略対称に配置されていてもよい。

【0028】

本発明の通信装置は、前記の課題を解決するために、上記の何れかに記載の弾性表面波装置を有していることを特徴としている。上記構成によれば、平衡度に優れた弾性表面波装置を有しているから、通信特性を向上できる。

【0029】

【発明の実施の形態】

本発明に係る弾性表面波装置の実施の一形態について図1に基づいて説明すれば、以下の通りである。本発明の弾性表面波装置は、図1に示すように、圧電基板501上に弾性表面波の伝搬方向に沿って形成された3つのIDTを有する縦結合共振子型弾性表面波フィルタ101を備え、前記縦結合共振子型弾性表面波フィルタ101の3つのIDTのうち中央に位置するIDT103を弾性表面波の伝搬方向に略対称に2分割してそれぞれを平衡信号端子108、109に接続し、極性を反転させた左右のIDT102、104を不平衡信号端子107に接続することで平衡－不平衡変換機能を持たせた弾性表面波装置において、前記平衡信号端子108、109の何れかに、圧電基板上に形成した、又はパッケージに形成した、もしくはパッケージに外付けしたリアクタンス成分120を並列に接続したことを特徴としている。

【0030】

上記構成においては、平衡－不平衡変換機能を有し、かつ平衡信号端子のインピーダンスが不平衡信号端子のインピーダンスの約4倍であり、さらに、リアクタンス成分120に

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よって平衡度を改善した弾性表面波装置が得られる。

【0031】

【実施例】

(実施例1)

図4ないし図7を用いて、本発明に係る実施例1の構成を説明する。なお、以後の実施例では、DCS受信用フィルタを例にとって説明を行っていく。まず、図4を用いて、実施例1の電極構成について説明する。実施例1では $40 \pm 5^\circ$ Ycut X伝搬LiTaO₃からなる圧電基板501上に、縦結合共振子型弾性表面波フィルタ401、及び縦結合共振子型弾性表面波フィルタ401に直列に接続された弾性表面波共振子402が、アルミニウム(A1)電極により、それぞれ形成されている。

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【0032】

縦結合共振子型弾性表面波フィルタ401の構成は、IDT404を弾性表面波の伝搬方向に沿って両側から挟み込むように各IDT403、405がそれぞれ形成され、さらにそれらの両側に各リフレクタ406、407がそれぞれ形成されている。

【0033】

IDT403は、帯状の基端部(バスバー)と、その基端部の一方の側部から直交する方向に延びる複数の、互いに平行な電極指とを備えたくし型電極を2つ備えており、上記各くし型電極の電極指の側部を互いに対面するように互いの電極指間に入り組んだ状態にて上記各くし型電極を有するものである。

【0034】

このようなIDT403では、各電極指の長さや幅、隣り合う各電極指の間隔、互いの電極指間での入り組んだ状態の対面長さを示す交叉幅を、それぞれ設定することにより信号変換特性や、通過帯域の設定が可能となっている。また、他の各IDTについても、IDT403と基本的な構造は同様である。リフレクタは、伝搬してきた弾性表面波を伝搬してきた方向に反射する機能を有するものである。

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【0035】

その上、上記構成では、図4を見るとわかるように、IDT403とIDT404との間近傍、及びIDT404とIDT405との間近傍における数本の電極指のピッチを、IDTの他の部分よりも小さくしている(図4の414、415の箇所)。

【0036】

さらに、中央のIDT404における一方のくし型電極は、弾性表面波の伝搬方向に2分割されて各くし型電極416、417となっており、それぞれのくし型電極416、417が各平衡信号端子412、413に接続されている。また、本実施例1では、IDT404における、くし型電極416、417と異なる、それらと対面している他方のくし型電極は、浮き電極としているが、アースに接地されたアース電極でもよい。IDT405は、IDT403に対して位相反転した構造となっている。これにより、上記構成は、平衡-不平衡変換機能を有している。

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【0037】

弾性表面波共振子402は、IDT408を挟み込むように、各リフレクタ409、410がそれぞれ形成されており、IDT408の一方のくし型電極が不平衡信号端子411に、IDT408の他方のくし型電極が各IDT403、405に接続されている。

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【0038】

図5に実施例1の、実際の圧電基板501上のレイアウトを示す。図5において、図4に対応する箇所は同じ番号を用いて示している。上記レイアウトでは、パッケージと導通を取るための各電極パッド502~506が設けられ、電極パッド502が不平衡信号端子411に対応するものであり、各電極パッド503、504がそれぞれ平衡信号端子412、413に相当するものであり、各電極パッド505、506がアース端子であり、各IDTは簡略化して図示されている。

【0039】

図6に、実施例1の構成を収納した、略直方体形状のパッケージ640の裏面(長形状

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） 640 a 側の各電極端子 641～645 をそれぞれ示す（弾性表面波装置（デバイス）の上面側から見た透視図で示している）。電極端子 641 は、裏面 640 a の長手方向における一方の端部の略中央に配置されている。各電極端子 642、643 は、裏面 640 a の長手方向における他方の端部の両隅部にそれぞれ配置されている。各電極端子 644、645 は、裏面 640 a の長手方向における両測部の略中央にそれぞれ配置されている。

【0040】

電極端子 641 が電極パッド 502 に接続される不平衡信号端子、各電極端子 642、643 がそれぞれ各電極パッド 503、504 に接続される平衡信号端子、各電極端子 644、645 がそれぞれ各電極端子 505、506 に接続されるアース端子である。

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【0041】

実施例 1 の弾性表面波装置は、図 7 に示すように、圧電基板 501 の電極面とパッケージ 640 のダイアタッチ面 653 との間をバンプ 656 で導通を取るフェイスダウン工法を用いて作製されている。

【0042】

パッケージ 640 は、長方形板状の底板 651 と、底板 651 の各辺部からそれぞれ互いに隣接して立設された各側壁部 652 と、各側壁部 652 の各上端部を密着して覆ってパッケージ 640 内を封止するためのキャップ 654 とを有している。

【0043】

実施例 1 の特徴は、図 5 に示すように、くし型電極 417 と電極パッド 504 とを接続する、帯状の引き回し配線 508 において、くし型電極 416 と電極パッド 503 とを接続する、帯状の引き回し配線 507 に対して、図 1 に示すリアクタンス成分 120 に相当する対地容量が大きくなるようにしている点である。

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【0044】

このように対地容量を大きくするため、本実施例 1 では、突出部 509 が、引き回し配線 508 から圧電基板 501 上にて外方に突出するように追加して設けられている。

【0045】

突出部 509 は、アース側の電極パッド 506 と IDT 405 とを接続する引き回し配線 511 に近接した位置の引き回し配線 508 から形成されていることが好ましい。

【0046】

また、突出部 509 は、上記引き回し配線 508 の長手方向に対して略直交し、上記引き回し配線 511 の長手方向に対して略平行に上記引き回し配線 511 と離間して伸びるように設けられていることが望ましい。

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【0047】

上記突出部 509 により、図 4 に示す、平衡信号端子 413 の対地容量は、平衡信号端子 412 より、例えば約 0.16 pF だけ大きくなることになり、よって、各引き回し配線 508、511 は、互いに非対称に形成されていることになる。

【0048】

このとき、IDT 404（各くし型電極 416、417）における、各 IDT 403、405 と隣り合っている電極指はそれぞれシグナル電極である。対地容量が大きくなる引き回し配線にしている電極パッド 504 に接続されているくし型電極 417 と、隣り合っている IDT 405 の電極指もシグナル電極である。一方、電極パッド 503 に接続されているくし型電極 416 と隣り合っている IDT 403 の電極指はアース電極である。

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【0049】

さらに、実施例 1 では、突出部 509 の非対称性以外の構成は、図 4 ないし図 6 に示した、2 分割した IDT 404 を中心に、弾性表面波の伝搬方向に対して垂直方向に設けた仮想軸 A に対して、圧電基板 501 上のレイアウト、パッケージ 640 のすべてが軸対称になるように設定されている。これにより、IDT 404 と隣り合う電極指の極性が IDT 403 と IDT 405 とで互いに異なっている点以外の不平衡成分が入らないようにしている。

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【0050】

縦結合共振子型弾性表面波フィルタ401の詳細な設計は、ピッチを小さくしていない電極指のピッチで決まる波長を λ I とすると、

交叉幅：78.9 λ I

IDT本数(403、404、405の順)：19(3)／(3)26(3)／(3)19本(カッコ内はピッチを小さくした電極指の本数)

リフレクタ本数：200本

duty：0.67(IDT、リフレクタ共)

電極膜厚：0.095 λ I

弾性表面波共振子402の詳細な設計は、以下のとおりである。

交叉幅：46.5 λ I

IDT本数：150本

リフレクタ本数：100本

duty：0.67

電極膜厚：0.097 λ I

次に、本実施例1の構成に関する作用・効果を説明する。図8に、実施例1の構成の位相平衡度を示す。比較としての比較例1は、図9に示すように、圧電基板501上のレイアウトを図5の実施例1に対して、引き回し配線508に対地容量が大きくなる箇所である突出部509を設けず、引き回し配線508を引き回し配線507と仮想軸Aに対して軸対称に設定した以外は、実施例1の構成と弾性表面波装置の設計、圧電基板501上のレイアウト、パッケージの実装方法等、すべて同じである。圧電基板501上のレイアウトを突出部無に変更した比較例1の位相平衡度も合わせて図8に示す。

【0051】

DCS受信用フィルタの通過帯域は、1805MHz～1880MHzである。この通過帯域の範囲内における位相平衡度のずれは、図8によると、比較例1では最大約22度であるのに対し、実施例1では最大約12度と、約10度位相平衡度が改善されている。これは平衡信号端子413の対地容量が大きくなるように調整することで、平衡信号端子412と平衡信号端子413との間における位相のずれが補正された効果である。

【0052】

実施例1では、引き回し配線508に対地容量が大きくなる箇所である突出部509を設けた。次に、これとは逆に、図10のように引き回し配線507に対地容量が大きくなる箇所としての突出部515を設け、平衡信号端子412の対地容量が約0.16pF大きくなった場合における位相平衡度を調査した。図10の場合の位相平衡度を図11に示す。比較として、図9に示した比較例1の場合の結果も図11に合わせて示す。

【0053】

平衡信号端子412の対地容量が大きくなるようにした場合、逆に比較例1よりも位相平衡度が悪化している。どちらの平衡信号端子の対地容量を大きくするかは、IDT402～404の、互いに隣り合う電極指の並び方、つまりシグナル電極同士、又はアース電極同士が互いに隣り合う無電界領域の有無により決めればよい。

【0054】

実施例1の場合は、IDT404における、各IDT403、405と隣り合っている電極指は、各くし型電極416、417の各シグナル電極である。一方、対地容量が大きくなる引き回し配線にしている、電極パッド504に接続されているくし型電極417と隣り合っているIDT405における、IDT404と隣り合っている電極指は、シグナル電極であり、対面するくし型電極417の最外電極指であるシグナル電極と無(小)電界領域を形成する。一方、電極パッド503に接続されているくし型電極416と隣り合っているIDT403における、IDT404と隣り合っている電極指は、アース電極であり、対面するくし型電極416の最外電極指であるシグナル電極と、上記無(小)電界領域より電界が大きいきが多い電界領域を形成する。

【0055】

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このような電極指の並びの場合、実施例1のように、無電界領域を最外電極指の近傍に（又は、上記最外電極指に面して）有するくし型電極417に接続されている平衡信号端子413の対地容量を、くし型電極416に接続されている平衡信号端子412より相対的に大きくなるように、例えば突出部509によって設定することで、位相平衡度を改善することができる。

【0056】

次に、図12のように、IDT704の各IDT703、705とそれぞれ隣り合っている各電極指が中性点電極（浮き電極でもアース電極でもよい）である場合について調査した。図13に、図12の電極構成の場合における図10に示す圧電基板501上のレイアウトの場合（実施例1の一変形例）の位相平衡度を示し、図14に、図12の電極構成の場合における図5に示すレイアウトの場合（比較例3）の位相平衡度を示す。比較例2として、図12の電極構成の場合における図9に示すレイアウト（突出部無）の場合における位相平衡度もそれぞれ比較例2として、図13及び図14に合わせて示す。図13及び図14は、突出部515、及び突出部509の箇所に約0.02pFの対地容量が入るよう

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にそれぞれ調整した場合の結果である。

【0057】

図12に示す電極指の並びの場合、図10に示すレイアウトのように、くし型電極716に接続されている平衡信号端子712の対地容量を、くし型電極717に接続されている平衡信号端子713より相対的に大きくなるようにすることで、位相平衡度が改善されていることがわかる。

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【0058】

次に、図12の電極構成において、各平衡信号端子に対し不平衡に、遅延線、及びインダクタンス成分を直列にそれぞれ付加した場合の位相平衡度をそれぞれ調査した。

【0059】

図15に、くし型電極716に接続されている平衡信号端子712に対して、図1に示すリアクタンス成分120としての遅延線720を付加した構成（実施例1の他の変形例）を示し、図16に、図1に示すリアクタンス成分120としてのインダクタンス成分722を付加した構成（実施例1のさらに他の変形例）を示す。

【0060】

図15及び図16の各構成における場合の位相平衡度を図17及び図18に示す。比較として、図12の構成における図9のレイアウトで遅延線もインダクタンス成分も付加していない場合の位相平衡度も比較例2として、図17及び図18にそれぞれ合わせて示す。

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【0061】

上記の遅延線720やインダクタンス成分722の具体的な形成方法は省略するが、例えば圧電基板上やパッケージ内の引き回し配線を長くした遅延線を設けたり、マイクロストリップ線路によるインダクタンス成分を設けたりすることが考えられる。

【0062】

また、可能であれば、例えば図31(a)及び図31(b)にそれぞれ示すように、パッケージ内部以外の外的位置に外付けしてもよい。図31(a)では、側壁部652と底板651との境界部分に、遅延線や、インダクタンス成分（リアクタンス成分）となる回路655が設けられ、図31(b)においては、底板651上に積層板657と、積層板657にその厚さ方向にビアホール658と、ビアホール658を介して接続され、底板651及び積層板657の間に形成された遅延線や、インダクタンス成分となる回路659とが設けられてもよい。

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【0063】

図17及び図18から明らかなように、遅延線720、インダクタンス成分722のいずれを挿入した場合においても、位相平衡度は比較例2に対して改善していることがわかる。なお、図4の電極構成においては、逆に平衡信号端子413に対して、遅延線720、又はインダクタンス成分722を付加してやればよい。

【0064】

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以上説明したように、実施例1では、圧電基板上に弾性表面波の伝搬方向に沿って形成された3つのIDTを有する縦結合共振子型弾性表面波フィルタを有し、3つのIDTのうち中央に位置するIDTを弾性表面波の伝搬方向に2分割し、左右のIDTの極性を反転させることで平衡-不平衡変換機能を持たせた弾性表面波装置において、対地容量、直列に接続するインダクタンス成分、及び遅延線の少なくとも一つであるリアクタンス成分を、2つの各平衡信号端子間で非対称とすることで、弾性表面波装置の位相平衡度を改善することができる。

【0065】

実施例1で対地容量を大きくする方法として、図5に示すように、圧電基板501上のシグナル電極をアース電極に近づける方法を示したが、これは図19のようにくし型電極で容量517を形成してもよい。また、パッケージ640内の引き回し配線を調整してもよい。

【0066】

また、実施例1では、余計な不平衡成分をなくすために平衡信号端子に対して、非対称に対地容量、インダクタンス成分、遅延線を付加する以外は、圧電基板501上のレイアウト、パッケージ640等は同じになるようにした。そのため、パッケージ640の裏面640a側における各電極端子641～645の数が5つの場合の例（図6参照）を示したが、本発明はこのようなパッケージに限らず、2分割した中央IDTを中心に弾性表面波の伝搬方向に垂直に引いた仮想軸Aに対して軸対称にできるパッケージであれば、どのようなパッケージを用いてもよい。

【0067】

例えば図20のように6つの電極端子801～806を有するパッケージ800の場合、電極端子801を不平衡信号端子、各電極端子802、803を平衡信号端子とし、各電極端子804～806をアース端子とすることで、仮想軸Aに対して軸対称とすることができる。

【0068】

その際、圧電基板501上のパターンレイアウトは図21のように、弾性表面波の伝搬方向を圧電基板501の長辺方向に沿ったものとし、圧電基板501上の電極パッド901を電極端子801に、電極パッド902を電極端子802に、電極パッド903を電極端子803に接続し、各電極パッド904～906をアース端子となる各電極端子804～806にそれぞれ接続することで、圧電基板501上も容易に仮想軸Aに対して軸対称とすることができる。

【0069】

また、実施例1では図7のように、フェイスダウン工法でパッケージと圧電基板の導通を取る方法で弾性表面波装置を作製したが、これはワイヤボンディング工法であっても問題はない。

【0070】

また、フェイスダウン工法で作製する構成としては図7の構成に限らず、例えば図22のように集合基板1001上に圧電基板1002をフリップチップ工法で接合し、その上に樹脂1003を覆って封止して、ダイシングにより1パッケージ単位に切断する構成、図23のように同じく集合基板1101上に圧電基板1102をフリップチップ工法で接合し、その上にシート状の樹脂材1103を覆って封止して、ダイシングにより1パッケージ単位に切断する構成で、弾性表面波装置が作製されていてもよい。

【0071】

実施例1では、3つのIDTを有する縦結合共振子型弾性表面波フィルタに、弾性表面波共振子を直列接続した構成を示したが、弾性表面波共振子が接続されていない構成や、さらには並列接続された構成においても、同様な効果が得られることは明らかである。また、図24のように、3つのIDTの両側に、さらにIDTを設けた、5IDTの縦結合共振子型の構成であってもよい。

【0072】

また、図25のように、IDTが隣り合っている付近の電極指130に対して重み付けを施してあっても、本発明の効果は得られる。図25の構成においては、さらに平衡度が改善される。重み付けの例として、図25では直列重み付けを用いているが、これは間引き重み付け、交叉幅重み付け、duty重み付けであってもよい。

【0073】

また、本発明では、図2のように、縦結合共振子型弾性表面波フィルタ101に、他の縦結合共振子型弾性表面波フィルタ201をカスケード接続した構成であってもよい。その際、縦結合共振子型弾性表面波フィルタ201の中央部に位置するIDT203は、総電極指本数が偶数本であることが望ましい。

【0074】

また、縦結合共振子型弾性表面波フィルタ101と縦結合共振子型弾性表面波フィルタ201とを互いに接続している各シグナルライン205、206を伝送する信号の位相が約180度異なるように、各IDT102、104、及び各IDT202、204の向きを調整しておくことが望ましい。上記の構成にすることで、さらに平衡度の優れた弾性表面波装置が得られる。

【0075】

図2の電極構成を用いる場合の圧電基板501上におけるレイアウトの例を、図6に示す5つの各電極端子を有するパッケージに実装する場合について図26、図27に、また、図20に示す6つの電極端子を有するパッケージに実装する場合について、図28、図29に示す。

【0076】

その際、各電極パッド1201、1301、1401、1501は不平衡信号端子、各電極パッド1202、1203、1302、1303、1402、1403、1502、1503を平衡信号端子に、残りをアース端子に接続する構成になる。

【0077】

実施例1では、 $40 \pm 5^\circ$ Ycut X伝搬LiTaO₃基板を圧電基板501として用いたが、効果が得られる原理からもわかるとおり、本発明はこの圧電基板501に限らず、 $64^\circ \sim 72^\circ$ Ycut X伝搬LiNbO₃、 41° Ycut X伝搬LiNbO₃などの圧電基板でも同様な効果が得られる。

【0078】

次に、本発明に係る、上記の実施例1及びその各変形例の何れか、又はそれらの特徴の組み合わせとなる、本発明の弾性表面波装置を用いた通信装置について図30に基づき説明する。

【0079】

図30に示すように、上記通信装置600は、受信を行うレシーバ側(Rx側)として、アンテナ601、アンテナ共用部/RFTOPフィルタ602、アンプ603、Rx段間フィルタ604、ミキサ605、1stIFフィルタ606、ミキサ607、2ndIFフィルタ608、1st+2ndローカルシンセサイザ611、TCXO(temperature compensated crystal oscillator(温度補償型水晶発振器))612、デバイダ613、ローカルフィルタ614を備えて構成されている。Rx段間フィルタ604からミキサ605へは、図30に二本線で示したように、バランス性を確保するために各平衡信号にて送信することが好ましい。

【0080】

また、上記通信装置600は、送信を行うトランシーバ側(Tx側)として、上記アンテナ601及び上記アンテナ共用部/RFTOPフィルタ602を共用するとともに、TxIFフィルタ621、ミキサ622、Tx段間フィルタ623、アンプ624、カプラ625、アイソレータ626、APC(automatic power control(自動出力制御))627を備えて構成されている。

【0081】

そして、上記のRx段間フィルタ604、1stIFフィルタ606、TxIFフィルタ

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621、Tx段間フィルタ623、アンテナ共用部／RFTopフィルタ602には、上述した本実施例の弾性表面波装置が好適に利用できる。

【0082】

本発明に係る弾性表面波装置は、フィルタ機能と共に不平衡－平衡変換機能を備え、その上、各平衡信号間の振幅特性や位相特性が理想により近いという優れた特性を有するものである。よって、上記弾性表面波装置を有する本発明の通信装置は、複合化された上記弾性表面波装置を用いたことにより、構成部品数を低減できて小型化できると共に、伝送特性を向上できるものとなっている。

【0083】

【発明の効果】

以上説明したように、本発明の弾性表面波装置は、圧電基板上に弾性表面波の伝搬方向に沿って形成された3つのIDTを有する縦結合共振子型弾性表面波フィルタであり、前記縦結合共振子型弾性表面波フィルタの3つのIDTのうち中央に位置するIDTを弾性表面波の伝搬方向に略対称に2分割してそれぞれを平衡信号端子に接続し、極性を反転させた左右のIDTを不平衡信号端子に接続することで平衡－不平衡変換機能を持たせた弾性表面波装置において、前記各平衡信号端子のいずれかに、圧電基板上に、パッケージに、及びパッケージに外付けの少なくとも一つにリアクタンス成分が接続されている構成である。

【0084】

それゆえ、上記構成は、各平衡信号端子のいずれかに対して、リアクタンス成分を接続することにより、各平衡信号端子間の平衡度を改善できるという効果を奏する。

【図面の簡単な説明】

【図1】 本発明の弾性表面波装置の構成図である。

【図2】 上記弾性表面波装置の一変形例（カスケード接続）の構成図である。

【図3】 従来の弾性表面波装置の構成図である。

【図4】 本発明の実施例1に係る弾性表面波装置の電極構成を示す構成図である。

【図5】 上記実施例1の弾性表面波装置における圧電基板上でのレイアウトを示す平面図である。

【図6】 上記実施例1の弾性表面波装置を収納したパッケージの裏面側での各端子の配置を、パッケージの上面（裏面の対向面）側からの透視図にてそれぞれ示す平面図である。

【図7】 上記実施例1の弾性表面波装置を収納したパッケージの断面図である。

【図8】 上記実施例1及び比較例1の各構成での位相平衡度をそれぞれ示すグラフである。

【図9】 上記比較例1の弾性表面波装置のレイアウトを示す平面図である。

【図10】 比較例2としての弾性表面波装置のレイアウトを示す平面図である。

【図11】 図10に示す構成（比較例2）及び上記比較例1の各構成での位相平衡度をそれぞれ示すグラフである。

【図12】 上記実施例1の一変形例としての弾性表面波装置に関する電極構成を示す構成図である。

【図13】 図12の電極構成を図10の圧電基板上のレイアウトで構成した場合、及び比較例2の周波数－位相平衡度をそれぞれ示すグラフである。

【図14】 図12の電極構成を図5の圧電基板上のレイアウトで構成した場合、及び比較例2の周波数－位相平衡度をそれぞれ示すグラフである。

【図15】 上記実施例1の他の変形例の弾性表面波装置を示す構成図である。

【図16】 上記実施例1のさらに他の変形例の弾性表面波装置を示す構成図である。

【図17】 図15の構成、及び比較例2の周波数－位相平衡度をそれぞれ示すグラフである。

【図18】 図16の構成、及び比較例2の周波数－位相平衡度をそれぞれ示すグラフである。

【図19】 上記実施例1のさらに他の変形例の弾性表面波装置を示す構成図である。

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【図20】上記実施例1のパッケージにおける各電極端子の配置に関する他の例を示す平面図である。

【図21】上記実施例1の弾性表面波装置のさらに他の変形例を示す構成図である。

【図22】上記実施例1の弾性表面波装置の、一製造プロセスを示す断面図である。

【図23】上記実施例1の弾性表面波装置の、他の製造プロセスを示す断面図である。

【図24】上記実施例1の弾性表面波装置のさらに他の変形例を示す構成図である。

【図25】上記実施例1の弾性表面波装置のさらに他の変形例を示す構成図である。

【図26】前記図2に示す電極構成を、図6に示す、裏面側の各電極端子を有するパッケージに実装する際の、圧電基板上のレイアウトの一例を示す平面図である。

【図27】上記図2に示す電極構成を、図6に示す、裏面側の各電極端子を有するパッケージに実装する際の、圧電基板上のレイアウトの他の例を示す平面図である。 10

【図28】前記図2に示す電極構成を、図20に示す、裏面側の各電極端子を有するパッケージに実装する際の、圧電基板上のレイアウトの一例を示す平面図である。

【図29】前記図2に示す電極構成を、図20に示す、裏面側の各電極端子を有するパッケージに実装する際の、圧電基板上のレイアウトの他の例を示す平面図である。

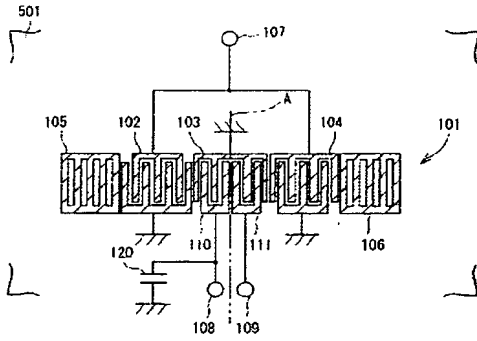
【図30】本発明に係る通信装置の要部ブロック図である。

【図31】上記実施例1の弾性表面波装置をパッケージに収納した際の、リアクタンス成分又は遅延線がパッケージに外付けされた場合の、上記パッケージの断面図であり、(a)は、底板と側壁部との間に上記リアクタンス成分又は遅延線としての回路が形成された例であり、(b)は、底板上にさらに積層板を形成した多層板内に上記リアクタンス成分又は遅延線が回路として形成された例である。 20

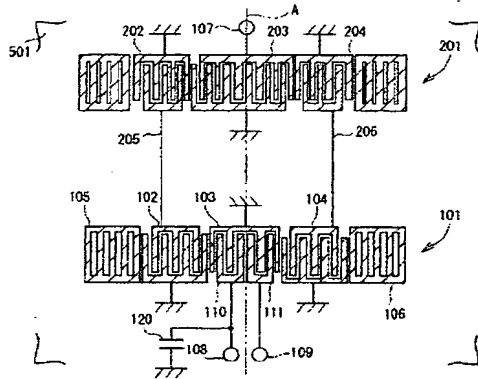
【符号の説明】

- 101 縦結合共振子型弾性表面波フィルタ
- 102、103、104 IDT（くし型電極部）
- 107 不平衡信号端子
- 108、109 平衡信号端子
- 120 リアクタンス成分
- 501 圧電基板

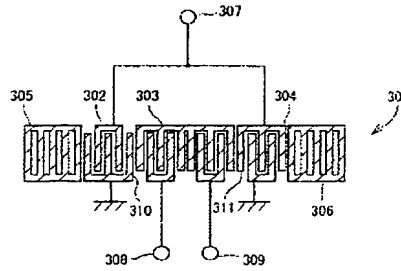
【図 1】



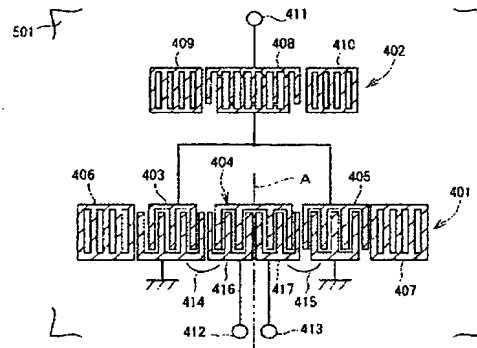
【図 2】



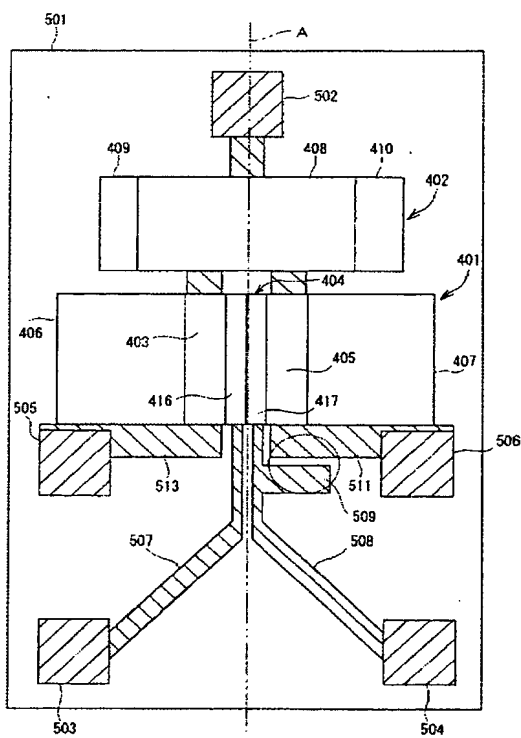
【図 3】



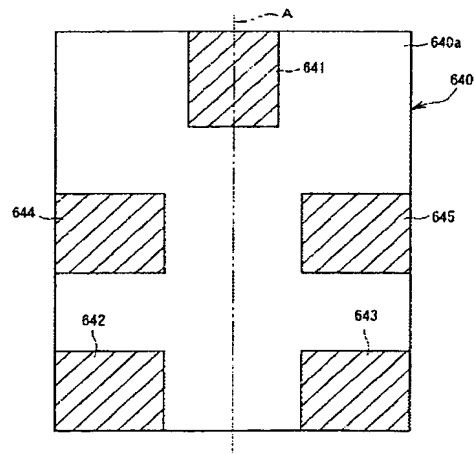
【図 4】



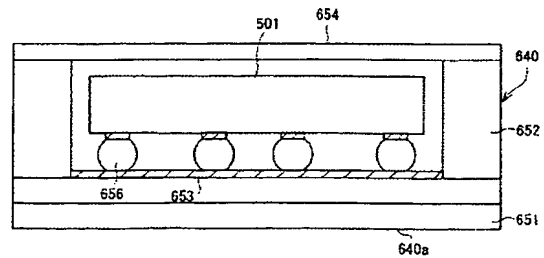
【図 5】



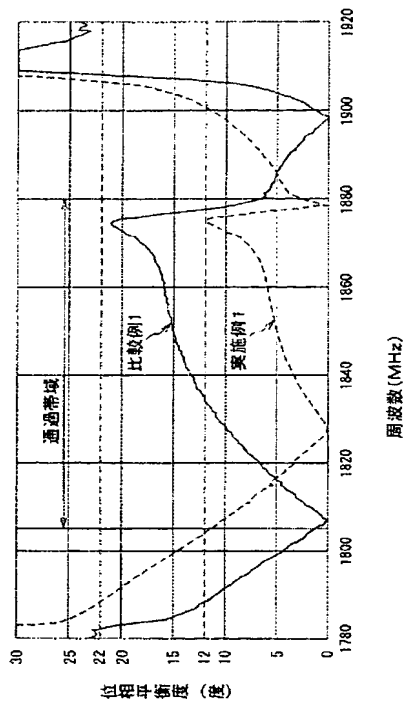
【図 6】



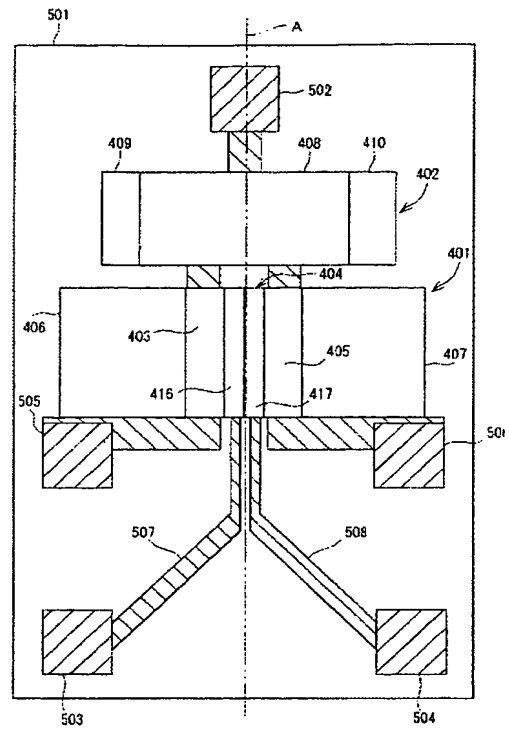
【図 7】



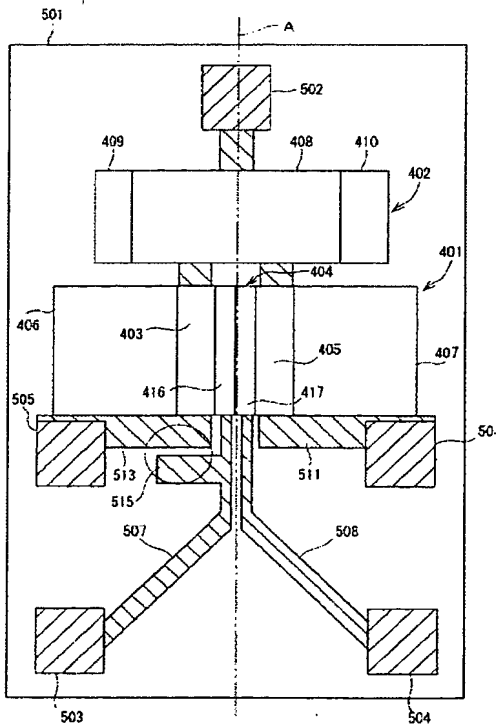
【図 8】



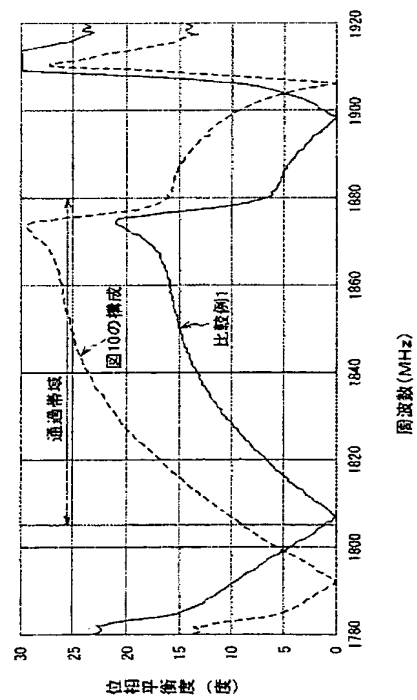
【図 9】



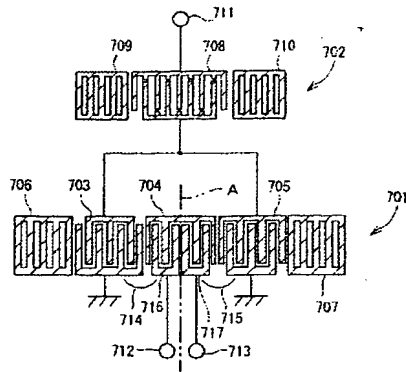
【図 10】



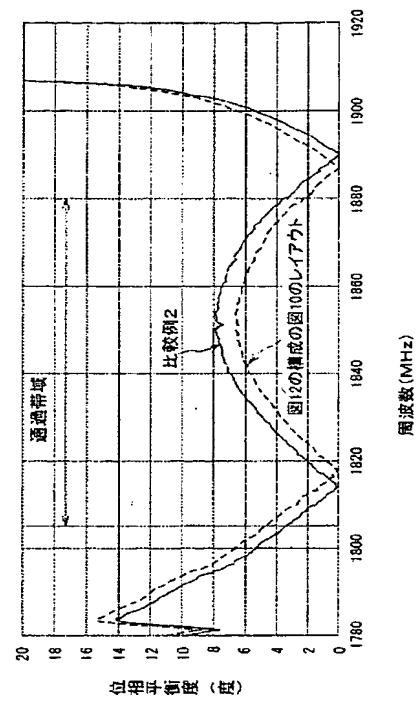
【図 11】



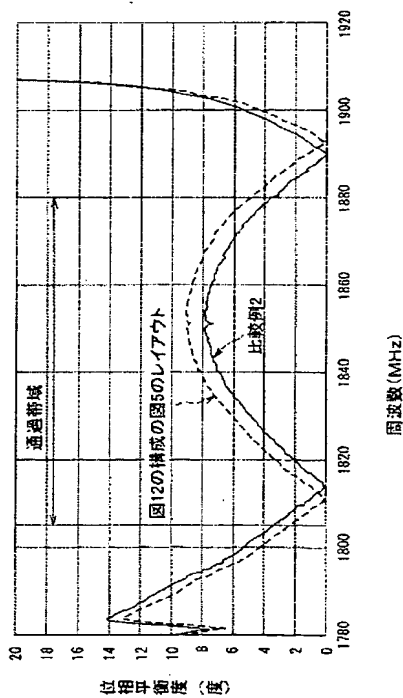
【図12】



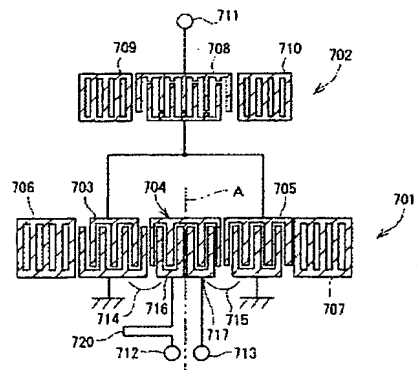
【図13】



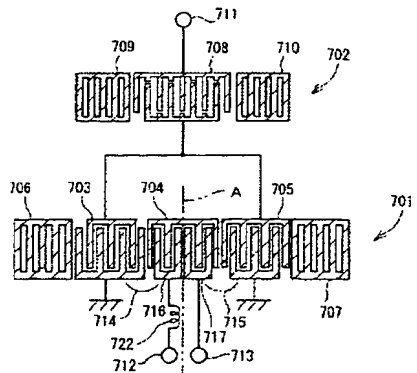
【図14】



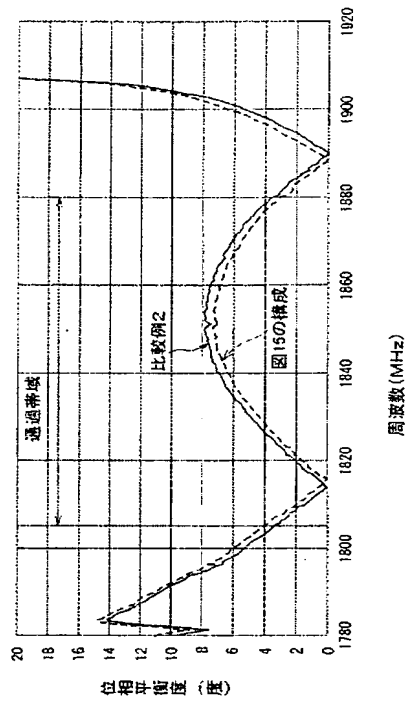
【図15】



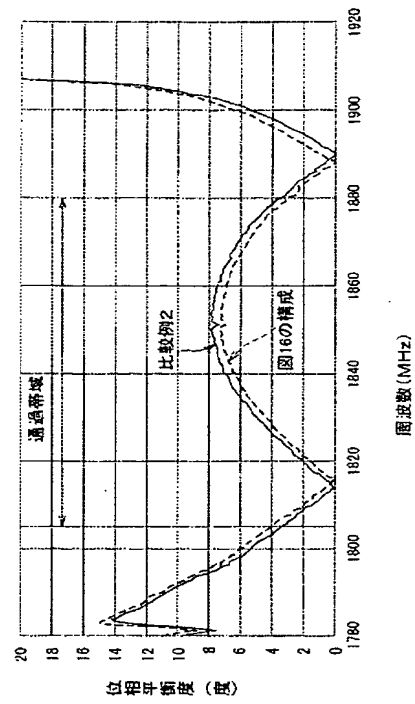
【図16】



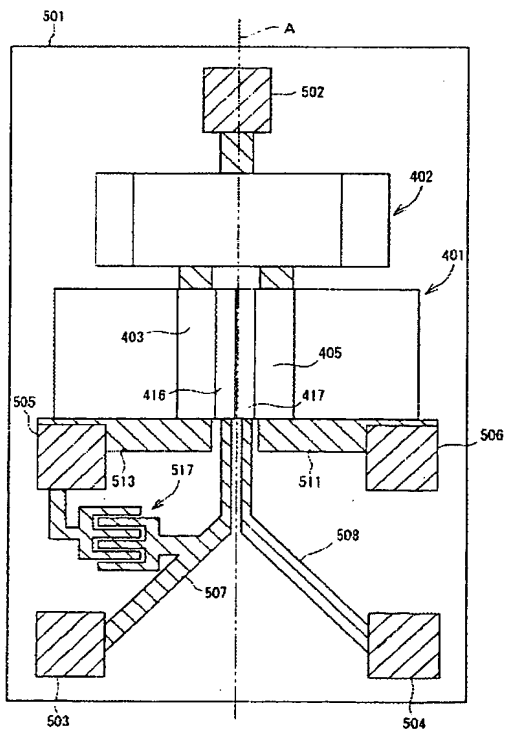
【図17】



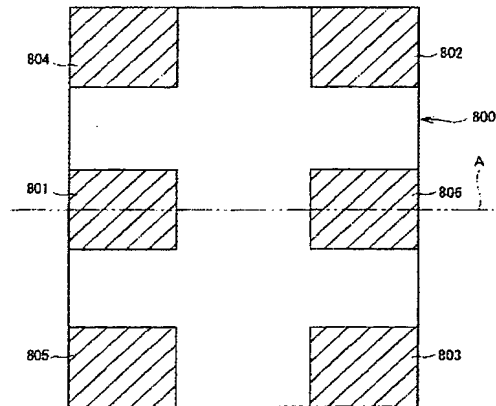
【図18】



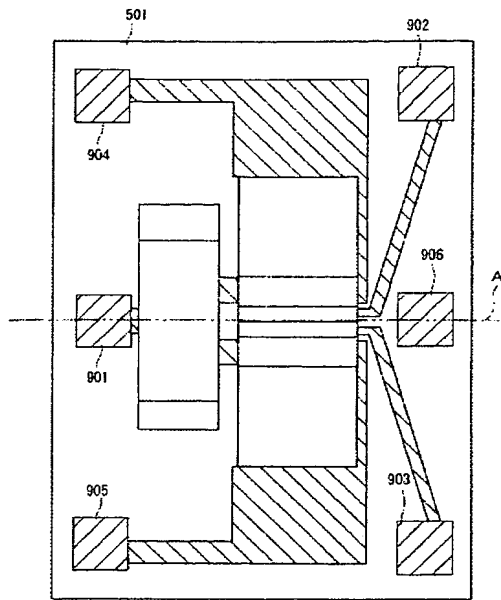
【図19】



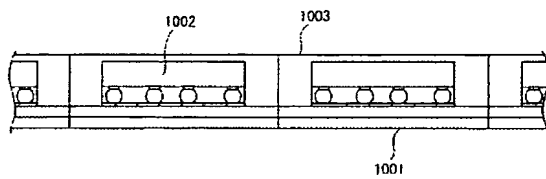
【図20】



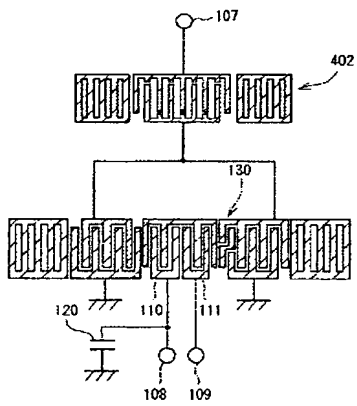
【図 2 1】



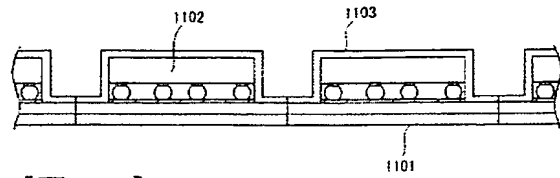
【図 2 2】



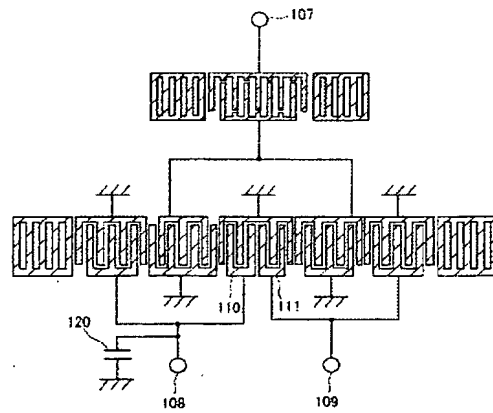
【図 2 5】



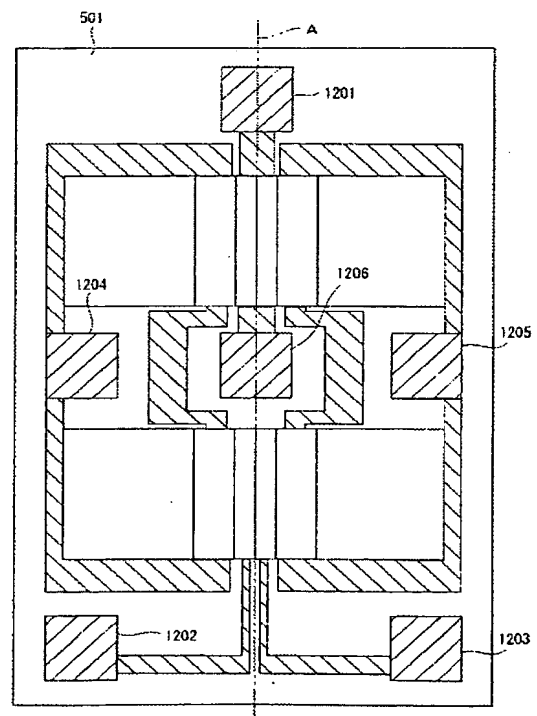
【図 2 3】



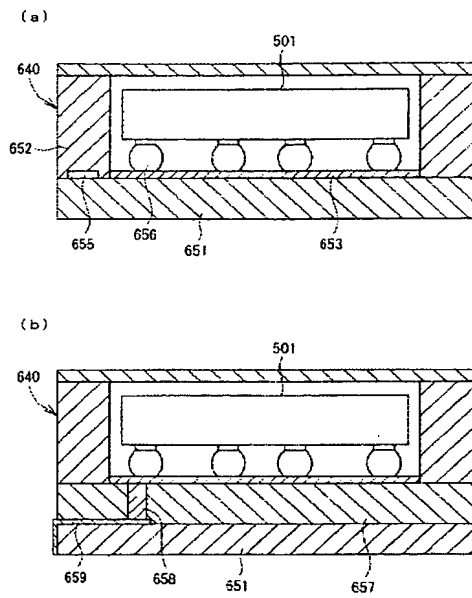
【図 2 4】



【図 2 6】



【図 31】



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3. In the drawings, any words are not translated.

CLAIMS

[Claim(s)]

[Claim 1]

It has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually,

The outermost electrode finger of the comb mold polar zone located in said center floats, and they are an electrode or the grounded electrode. the comb mold polar zone located in said center is adjoined -- two going away and among mold polar zone Surface acoustic wave equipment characterized by forming leading-about wiring asymmetrically so that parasitic capacitance may become [the direction of the balanced signal terminal located in the side near the comb mold polar zone by which the outermost electrode finger which adjoins the comb mold polar zone located in said center is grounded] large relatively.

[Claim 2]

It has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal

terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually,

The outermost electrode finger of the comb mold polar zone located in said center is a signal electrode,

Surface acoustic wave equipment characterized by to form leading-about wiring asymmetrically so that parasitic capacitance may become [the direction of the balanced signal terminal located in the side near the comb mold polar zone whose outermost electrode finger which adjoins the comb mold polar zone which adjoins the comb mold polar zone located in said center, and which goes away two and is located in said center among mold polar zone is a signal electrode] large relatively.

[Claim 3]

Surface acoustic wave equipment according to claim 1 or 2 which said piezo-electric substrate is carried in the package by flip chip bonding, and is characterized by the thing which were made into said asymmetry, and for which it takes about and wiring is formed in this package.

[Claim 4]

Surface acoustic wave equipment given in claim 1 thru/or any 1 term of 3 characterized by forming leading-about wiring of a package on said piezo-electric substrates other than said unsymmetrical leading-about wiring in the core of the comb mold polar zone located in said center at the abbreviation symmetry to the virtual shaft perpendicularly established to the propagation direction of a surface acoustic wave.

[Claim 5]

It has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually,

The outermost electrode finger of the comb mold polar zone located in

said center floats, and they are an electrode or the grounded electrode, Surface acoustic wave equipment characterized by adding a reactance component or the delay line to the balanced signal terminal located in the side near the comb mold polar zone by which the outermost electrode finger which adjoins the comb mold polar zone which adjoins the comb mold polar zone located in said center, and which goes away two and is located in said center among mold polar zone is grounded.

[Claim 6]

It has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually,

The outermost electrode finger of the comb mold polar zone located in said center is a signal electrode,

Surface acoustic wave equipment characterized by adding a reactance component or the delay line to the balanced signal terminal located in the side near the comb mold polar zone whose outermost electrode finger which adjoins the comb mold polar zone which adjoins the comb mold polar zone located in said center, and which goes away two and is located in said center among mold polar zone is a signal electrode.

[Claim 7]

Surface acoustic wave equipment according to claim 5 or 6 which said piezo-electric substrate is carried in the package by flip chip bonding, and is characterized by forming said reactance component or delay line in this package.

[Claim 8]

Surface acoustic wave equipment given in claim 5 thru/or any 1 term of 7 characterized by setting leading-about wiring on said reactance component or said piezo-electric substrates other than the delay line, and a package as the abbreviation symmetry to the virtual shaft prepared in the core of the comb mold polar zone located in said center at right angles to the propagation direction of a surface acoustic wave.

[Claim 9]

Surface acoustic wave equipment given in claim 5 thru/or any 1 term of 8 to which said reactance component is a capacitance component, and is characterized by connecting with juxtaposition between said balanced signal terminals and ground potentials.

[Claim 10]

Surface acoustic wave equipment given in claim 5 thru/or any 1 term of 8 to which said reactance component is an inductance component, and is characterized by connecting with said balanced signal terminal at the serial.

[Claim 11]

Surface acoustic wave equipment given in claim 1 thru/or any 1 term of 10 characterized by adding the surface acoustic wave resonator to a serial and/or juxtaposition to said surface acoustic wave filter.

[Claim 12]

Surface acoustic wave equipment given in claim 1 thru/or any 1 term of 11 to which said surface acoustic wave filter is characterized by plurality and carrying out cascade connection mutually.

[Claim 13]

Surface acoustic wave equipment according to claim 12 characterized by the total electrode finger number of said surface acoustic wave filter which carried out cascade connection being even.

[Claim 14]

Surface acoustic wave equipment according to claim 12 or 13 characterized by being set up so that the phases of the signal with which it connects through a signal line, respectively, and the comb mold polar zone located in each both ends of each aforementioned surface acoustic wave filter by which cascade connection was carried out transmits this each signal line may differ about 180 degrees mutually.

[Claim 15]

Surface acoustic wave equipment given in claim 1 thru/or any 1 term of 14 characterized by carrying out weighting of the electrode finger near the contiguity [in / it goes away one side at least, and / the mold polar zone] section when it is the comb mold polar zone which adjoins each other mutually among said surface acoustic wave filters.

[Claim 16]

Surface acoustic wave equipment according to claim 15 characterized by said weighting being serial weighting.

[Claim 17]

Said piezo-electric substrate is carried in the package by flip chip bonding. The external terminal of this package As opposed to the virtual shaft which is six, one unbalance signal terminal, two balanced signal

terminals, and three grounding terminals, and six terminals prepared in the core of the comb mold polar zone located in the center of said surface acoustic wave filter perpendicularly to the propagation direction of a surface acoustic wave Surface acoustic wave equipment given in claim 1 thru/or any 1 term of 16 characterized by being arranged at the abbreviation symmetry.

[Claim 18]

Said piezo-electric substrate is carried in the package by flip chip bonding. The external terminal of this package As opposed to the virtual shaft which is five, one unbalance signal terminal, two balanced signal terminals, and two grounding terminals, and five terminals prepared in the core of the comb mold polar zone located in the center of said surface acoustic wave filter perpendicularly to the propagation direction of a surface acoustic wave Surface acoustic wave equipment given in claim 1 thru/or any 1 term of 16 characterized by being arranged at the abbreviation symmetry.

[Claim 19]

The communication device characterized by having surface acoustic wave equipment of a publication in claim 1 thru/or any 1 term of 18.

[Translation done.]

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DETAILED DESCRIPTION

[Detailed Description of the Invention]

[0001]

[Field of the Invention]

This invention relates to surface acoustic wave equipment equipped with the surface acoustic wave filter which has balanced - unbalance conversion function.

[0002]

[Description of the Prior Art]

The technical progress over the miniaturization of a portable telephone (communication device) in recent years and lightweight-izing has a remarkable thing. As a means for realizing this, development of the components which compounded the function of plurality [miniaturization / reduction of each component parts and] from the first has also progressed.

[0003]

Against the background of such a situation, what gave balanced - unbalance conversion function and the function of the so-called balun to the surface acoustic wave equipment used for RF stage of a portable telephone is studied briskly in recent years, and has come to be used focusing on GSM (Global System for Mobile communications) etc.

[0004]

It applies also for some patents about the surface acoustic wave equipment which gave such a balanced - unbalance conversion function. The impedance by the side of an unbalance signal terminal currently indicated by drawing 3 at JP, 11-97966, A shows the surface acoustic wave equipment which the impedance by the side of 50 ohms and a balanced signal terminal gave balanced - unbalance conversion function in which it was set as 200 ohms.

[0005]

In the vertical joint resonator mold surface acoustic wave filter 301 with which the configuration of drawing 3 has the comb mold polar zone (it is called IDT Inter-Digital Transducer and the following) along three and the propagation direction of a surface acoustic wave IDT303 located in the center was divided into two in the propagation direction of a surface acoustic wave at the abbreviation symmetry, each was connected to the balanced signal terminals 308 and 309, and each IDT 302 and 304 of the right and left which reversed the polarity is connected to the unbalance signal terminal 307. Thereby, in the above-mentioned configuration, by polar reversal, balanced - unbalance conversion function can be given and the impedance by the side of a balanced signal terminal can be further made comparatively more into about 4 times of the impedance by the side of an unbalance signal terminal for 2 minutes of IDT303.

[0006]

With the filter which has balanced - unbalance conversion function, in the transmission characteristic in the passband between an unbalance signal terminal and each terminal of a balanced signal terminal, the amplitude characteristic is equal, and it is required that the phase

should be reversed 180 degrees and it is calling it amplitude unbalance and phase unbalance, respectively.

[0007]

With amplitude unbalance and phase unbalance, the filter equipment which has said balanced - unbalance conversion function is considered to be the device of three ports. For example, amplitude unbalance $=|A|$ [when making each of a port 1 and a balanced output terminal into a port 2 and a port 3] and $A=|20\log(S_{21})|-|20\log(S_{31})|$, phase unbalance $=|B-180|$, and $B=|S_{21}-S_{31}|$ defines an unbalanced input terminal. As for such unbalance, amplitude unbalance is ideally made into 0 times in the passband of a surface acoustic wave filter, as for 0dB and phase unbalance.

[0008]

[Problem(s) to be Solved by the Invention]

However, there was a problem that unbalance was bad, in the conventional configuration shown in drawing 3. The reason is because IDT302 differ in the polarity of the electrode finger which adjoins IDT303 mutually from IDT304 (310 and 311 of drawing 3) and parasitic capacitance, bridge capacity, etc. included in each of each balanced signal terminals 308 and 309 differ from each other mutually by this.

[0009]

The purpose of this invention is to solve the above-mentioned problem in the configuration of drawing 3, and have balanced - unbalance conversion function in which unbalance has been improved, and offer the surface acoustic wave equipment whose impedance of a balanced signal terminal is about 4 times the impedance of an unbalance signal terminal.

[0010]

[Means for Solving the Problem]

In order that the surface acoustic wave equipment of this invention may solve the above technical problem, it has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed

mutually The outermost electrode finger of the comb mold polar zone located in said center floats, and they are an electrode or the grounded electrode. the comb mold polar zone located in said center is adjoined -- two going away and among mold polar zone It is characterized by forming leading-about wiring asymmetrically so that parasitic capacitance may become [the direction of the balanced signal terminal located in the side near the comb mold polar zone by which the outermost electrode finger which adjoins the comb mold polar zone located in said center is grounded] large relatively.

[0011]

The unbalance between each balance signal terminals, especially phase unbalance are improvable by forming leading-about wiring asymmetrically so that parasitic capacitance may become [the direction of the balance signal terminal located in the side near the comb mold polar zone by which the outermost electrode finger which adjoins the comb / which adjoins the comb mold polar zone which is located in said center according to the above-mentioned configuration / mold polar zone which goes away two and is located in said center among mold polar zone is grounded] large relatively.

[0012]

In order that other surface acoustic wave equipments of this invention may solve the above technical problem, it has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced -- unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually The outermost electrode finger of the comb mold polar zone located in said center is a signal electrode. the comb mold polar zone located in said center is adjoined -- two going away and among mold polar zone It is characterized by forming leading-about wiring asymmetrically so that parasitic capacitance may become [the direction of the balanced signal terminal located in the side near the comb mold polar zone whose outermost electrode finger which adjoins the comb mold polar zone located in said center is a signal electrode] large

relatively.

[0013]

according to the above-mentioned configuration, the comb mold polar zone located in said center is adjoined -- two going away and among mold polar zone. Relatively, the direction of the balanced signal terminal located in the side near the comb mold polar zone whose outermost electrode finger which adjoins the comb mold polar zone located in said center is a signal electrode so that parasitic capacitance may become large. By forming leading-about wiring asymmetrically, the unbalance, especially phase unbalance between each balanced signal terminal are improvable.

[0014]

With the above-mentioned surface acoustic wave equipment, said piezo-electric substrate is carried in the package by flip chip bonding, and leading-about wiring made into said asymmetry may be formed in this package.

[0015]

In the above-mentioned surface acoustic wave equipment, leading-about wiring of a package on said piezo-electric substrates other than said unsymmetrical leading-about wiring may be formed in the core of the comb mold polar zone located in said center at the abbreviation symmetry to the virtual shaft perpendicularly established to the propagation direction of a surface acoustic wave.

[0016]

In order that the surface acoustic wave equipment of further others of this invention may solve the above technical problem. It has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually. The outermost electrode finger of the comb mold polar zone located in said center floats, and they are an electrode or the grounded electrode. It is characterized by adding a reactance component or the delay line to the balanced signal terminal located in

the side near the comb mold polar zone by which the outermost electrode finger which adjoins the comb mold polar zone which adjoins the comb mold polar zone located in said center, and which goes away two and is located in said center among mold polar zone is grounded.

[0017]

According to the above-mentioned configuration, the unbalance, especially phase unbalance between each balanced signal terminal are improvable by having added a reactance component or the delay line to the balanced signal terminal located in the side near the comb mold polar zone by which the outermost electrode finger which adjoins the comb mold polar zone located in the center is grounded.

[0018]

In order that the surface acoustic wave equipment of further others of this invention may solve the above technical problem It has the comb mold polar zone of three or more odd number individuals formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Are said comb mold polar zone which goes away odd pieces and is located in the center among mold polar zone, while go away, divide a mold electrode into two in the propagation direction of a surface acoustic wave, and each is connected to a balanced signal terminal. In surface acoustic wave equipment equipped with the surface acoustic wave filter of the vertical joint resonator mold which has balanced - unbalance conversion function connected to the unbalance signal terminal while two go away and the mold polar zone has the structure which adjoins the comb mold polar zone located in the center of this, and which was reversed mutually The outermost electrode finger of the comb mold polar zone located in said center is a signal electrode. the comb mold polar zone located in said center is adjoined -- two going away and among mold polar zone It is characterized by adding a reactance component or the delay line to the balanced signal terminal located in the side near the comb mold polar zone whose outermost electrode finger which adjoins the comb mold polar zone located in said center is a signal electrode.

[0019]

According to the above-mentioned configuration, the outermost electrode finger of the comb mold polar zone located in the center is a signal electrode. the comb mold polar zone located in said center is adjoined - two going away and among mold polar zone By having added a reactance component or the delay line to the balanced signal terminal located in the side near the comb mold polar zone whose outermost electrode finger which adjoins the comb mold polar zone located in said center is a

signal electrode, the unbalance, especially phase unbalance between each balanced signal terminal are improvable.

[0020]

With the above-mentioned surface acoustic wave equipment, said piezo-electric substrate is carried in the package by flip chip bonding, and said reactance component or delay line may be formed in this package.

[0021]

In the above-mentioned surface acoustic wave equipment, leading-about wiring on said reactance component or said piezo-electric substrates other than the delay line, and a package may be set as the abbreviation symmetry to the virtual shaft prepared in the core of the comb mold polar zone located in said center at right angles to the propagation direction of a surface acoustic wave.

[0022]

With the above-mentioned surface acoustic wave equipment, said reactance component is a capacitance component and may be connected to juxtaposition between said balanced signal terminals and ground potentials. In the above-mentioned surface acoustic wave equipment, said reactance component is an inductance component and may be connected to said balanced signal terminal at the serial.

[0023]

With the above-mentioned surface acoustic wave equipment, the surface acoustic wave resonator may be added to a serial and/or juxtaposition to said surface acoustic wave filter. In the above-mentioned surface acoustic wave equipment, cascade connection of said surface acoustic wave filter may be carried out to two or more each other. It is desirable that the total electrode finger number of said surface acoustic wave filter which carried out cascade connection is even with the above-mentioned surface acoustic wave equipment.

[0024]

In the above-mentioned surface acoustic wave equipment, it is desirable to be set up so that the phases of the signal with which it connects through a signal line, respectively, and the comb mold polar zone located in each both ends of each aforementioned surface acoustic wave filter by which cascade connection was carried out transmits this each signal line may differ about 180 degrees mutually.

[0025]

With the above-mentioned surface acoustic wave equipment, weighting of the electrode finger near the contiguity [in / it goes away one side at least, and / the mold polar zone] section it is [contiguity] the comb mold polar zone which adjoins each other mutually among said surface

acoustic wave filters may be carried out. In the above-mentioned surface acoustic wave equipment, said weighting may be serial weighting.

[0026]

In the above-mentioned surface acoustic wave equipment, said piezo-electric substrate is carried in the package by flip chip bonding. The external terminal of this package It is six, one unbalance signal terminal, two balanced signal terminals, and three grounding terminals, and six terminals may be arranged at the abbreviation symmetry to the virtual shaft perpendicularly prepared in the core of the comb mold polar zone located in the center of said surface acoustic wave filter to the propagation direction of a surface acoustic wave.

[0027]

With the above-mentioned surface acoustic wave equipment, said piezo-electric substrate is carried in the package by flip chip bonding, the external terminal of this package is five, one unbalance signal terminal, two balanced signal terminals, and two grounding terminals, and five terminals may be arranged at the abbreviation symmetry to the virtual shaft perpendicularly prepared in the core of the comb mold polar zone located in the center of said surface acoustic wave filter to the propagation direction of a surface acoustic wave.

[0028]

The communication device of this invention is characterized by having surface acoustic wave equipment given in above any they are, in order to solve the aforementioned technical problem. According to the above-mentioned configuration, since it has surface acoustic wave equipment excellent in unbalance, a communication link property can be improved.

[0029]

[Embodiment of the Invention]

It will be as follows if one gestalt of operation of the surface acoustic wave equipment concerning this invention is explained based on drawing 1 . The surface acoustic wave equipment of this invention is equipped with the vertical joint resonator mold surface acoustic wave filter 101 which has three IDT(s) formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate 501 as shown in drawing 1 . Divide into two IDT103 located in the center among three IDT(s) of said vertical joint resonator mold surface acoustic wave filter 101 in the propagation direction of a surface acoustic wave at the abbreviation symmetry, and each is connected to the balanced signal terminals 108 and 109. In the surface acoustic wave equipment which gave balanced - unbalance conversion function by connecting to the unbalance signal terminal 107 IDT 102 and 104 of the right and left which reversed

the polarity Or it formed on the piezo-electric substrate any of said balanced signal terminals 108 and 109 they are, it is characterized by connecting to juxtaposition the reactance component 120 which formed or carried out external to the package at the package.

[0030]

In the above-mentioned configuration, it has balanced - unbalance conversion function, and the impedance of a balanced signal terminal is about 4 times the impedance of an unbalance signal terminal, and the surface acoustic wave equipment which has improved unbalance by the reactance component 120 is obtained further.

[0031]

[Example]

(Example 1)

The configuration of the example 1 concerning this invention is explained using drawing 4 thru/or drawing 7 . In addition, future examples explain taking the case of the filter for DCS reception. First, the electrode configuration of an example 1 is explained using drawing 4 . In the example 1, the surface acoustic wave resonator 402 connected to the vertical joint resonator mold surface acoustic wave filter 401 and the vertical joint resonator mold surface acoustic wave filter 401 at the serial is formed with the aluminum (aluminum) electrode, respectively on the piezo-electric substrate 501 which consists of 40 **5-degreeYcutX propagation LiTaO₃.

[0032]

Each IDT 403 and 405 is formed, respectively so that the configuration of the vertical joint resonator mold surface acoustic wave filter 401 may put IDT404 from both sides along the propagation direction of a surface acoustic wave, and each reflectors 406 and 407 are further formed in those both sides, respectively.

[0033]

IDT403 wanted to have the parallel electrode finger of each other of plurality which is prolonged in the direction which intersects perpendicularly from the band-like end face section (bus bar) and one flank of the end face section, was carried out, is equipped with two mold electrodes, and has each above-mentioned comb mold electrode in the condition of having become intricate between mutual electrode fingers so that the flank of the electrode finger of each above-mentioned comb mold electrode might be met mutually.

[0034]

In such IDT403, a signal transformation property and a setup of a passband are possible by setting up the decussation width of face which

shows the die length and width of face of each electrode finger, spacing of each adjacent electrode finger, and the confrontation die length in the condition between mutual electrode fingers of having become intricate, respectively. Moreover, IDT403 and fundamental structure are the same about each of other IDT. A reflector has the function reflected in the direction which has spread the spread surface acoustic wave.

[0035]

Moreover, with the above-mentioned configuration, the pitch of several electrode fingers by the side of the nearness of IDT403 and IDT404 and the nearness of IDT404 and IDT405 is made smaller than other parts of IDT so that it may turn out that drawing 4 is seen (414 of drawing 4 , 415 parts).

[0036]

Furthermore, it goes away in IDT404 of a center, and a mold electrode is carried out in the propagation direction of a surface acoustic wave 2 ****s, it has become each comb mold electrodes 416 and 417, and each comb mold electrode 416 and 417 is connected to each balanced signal terminals 412 and 413. Moreover, in this example 1, although a different comb mold electrode of another side which has met them from the comb mold electrodes 416 and 417 in IDT404 is used as the float electrode, the ground electrode grounded by the ground is sufficient as it. IDT405 has structure which carried out phase inversion to IDT403. Thereby, the above-mentioned configuration has balanced - unbalance conversion function.

[0037]

Each reflectors 409 and 410 are formed, respectively, one comb mold electrode of IDT408 is connected to the unbalance signal terminal 411, and the comb mold electrode of another side of IDT408 is connected to each IDT 403 and 405 so that the surface acoustic wave resonator 402 may put IDT408.

[0038]

The layout on the actual piezo-electric substrate 501 of an example 1 is shown in drawing 5 . In drawing 5 , the part corresponding to drawing 4 is shown using the same number. With the above-mentioned layout, each electrode pads 502-506 for taking a package and a flow are formed, the electrode pad 502 corresponds to the unbalance signal terminal 411, each electrode pads 503 and 504 are equivalent to the balanced signal terminals 412 and 413, respectively, each electrode pads 505 and 506 are grounding terminals, and each IDT is simplified and illustrated.

[0039]

Each electrode terminals 641-645 by the side of rear-face (shape of

rectangle) 640a of the package 640 of the abbreviation rectangular parallelepiped configuration which contained the configuration of an example 1 to drawing 6 are shown, respectively (the perspective drawing seen from the top-face side of surface acoustic wave equipment (device) shows). The electrode terminal 641 is arranged in the center of abbreviation of an edge in the longitudinal direction of rear-face 640a. Each electrode terminals 642 and 643 are arranged in both the corners of the other-end section in the longitudinal direction of rear-face 640a, respectively. Each electrode terminals 644 and 645 are arranged, respectively in the center of abbreviation of both **** in the longitudinal direction of rear-face 640a.

[0040]

They are the unbalance signal terminal by which an electrode terminal 641 is connected to the electrode pad 502, the balanced signal terminal by which each electrode terminals 642 and 643 are connected to each electrode pads 503 and 504, respectively, and the grounding terminal by which each electrode terminals 644 and 645 are connected to each electrode terminals 505 and 506, respectively.

[0041]

The surface acoustic wave equipment of an example 1 is produced using the face down method of construction which takes a flow by the bump 656 in between the electrode surface of the piezo-electric substrate 501, and the diamond touch sides 653 of a package 640, as shown in drawing 7 .

[0042]

The package 640 has the cap 654 for sticking and covering the rectangular plate-like bottom plate 651, each side-attachment-wall section 652 which adjoined mutually, respectively and was set up from each **** of a bottom plate 651, and each upper limit section of each side-attachment-wall section 652, and closing the inside of a package 640.

[0043]

The description of an example 1 is the point of trying for the earth capacity which is equivalent to the reactance component 120 shown in drawing 1 to the band-like leading-about wiring 507 which connects the comb mold electrode 417 and the electrode pad 504, and which connects the comb mold electrode 416 and the electrode pad 503 in the band-like leading-about wiring 508 to become large, as shown in drawing 5 .

[0044]

Thus, by this example 1, in order to enlarge earth capacity, the lobe 509 is formed in addition so that it may project in the method of outside on the piezo-electric substrate 501 from the leading-about

wiring 508.

[0045]

As for a lobe 509, it is desirable to be formed from the leading-about wiring 508 of the location close to the leading-about wiring 511 which connects the electrode pad 506 and IDT405 by the side of a ground.

[0046]

Moreover, as for a lobe 509, it is desirable to be prepared so that an abbreviation rectangular cross is carried out to the longitudinal direction of the above-mentioned leading-about wiring 508, and it may estrange with the above-mentioned leading-about wiring 511 to abbreviation parallel and may be extended to them to the longitudinal direction of the above-mentioned leading-about wiring 511.

[0047]

By the above-mentioned lobe 509, only about 0.16pF of earth capacity of the balanced signal terminal 413 shown in drawing 4 will become large from the balanced signal terminal 412, and, therefore, each leading-about wiring 508 and 511 will be formed asymmetrically mutually.

[0048]

At this time, each electrode finger in IDT404 (each comb mold electrodes 416 and 417) which adjoins IDT 403 and 405 is a signal electrode, respectively. The electrode finger of IDT405 which adjoins the comb mold electrode 417 connected to the electrode pad 504 made leading-about wiring with which earth capacity becomes large is also a signal electrode. The electrode finger of IDT403 which, on the other hand, adjoins the comb mold electrode 416 connected to the electrode pad 503 is a ground electrode.

[0049]

Furthermore, in the example 1, to the virtual shaft A which was shown in drawing 4 thru/or drawing 6 and which was perpendicularly established to the propagation direction of a surface acoustic wave focusing on IDT404 divided into two, the configuration of those other than the asymmetry of a lobe 509 is set up so that the layout on the piezo-electric substrate 501 and all the packages 640 may become axial symmetry. He is trying for unbalance components other than the point that IDT403 differ in the polarity of the electrode finger which adjoins IDT404 mutually from IDT405 by this not to enter.

[0050]

If the detailed design of the vertical joint resonator mold surface acoustic wave filter 401 sets to $\lambda/4$ wavelength decided by the pitch of the electrode finger which has not made the pitch small,
Decussation width of face: $78.9\lambda/4$

IDT number (order of 403, 404, and 405): -- (3)1919(3) / (3)26(3)
(number of the electrode finger with which the inside of a parenthesis made the pitch small)

Reflector number: 200

duty: 0.67 (IDT and reflector)

Electrode-layer thickness: 0.095λ

The detailed design of the surface acoustic wave resonator 402 is as follows.

Decussation width of face: 46.5λ

IDT number: 150

Reflector number: 100

duty: 0.67

Electrode-layer thickness: 0.097λ

Next, the operation and effectiveness about the configuration of this example 1 are explained. The phase unbalance of the configuration of an example 1 is shown in drawing 8. As shown in drawing 9, the configuration of an example 1, the design of surface acoustic wave equipment, the layout on the piezo-electric substrate 501, the mounting approach of a package of the example 1 of a comparison as a comparison, etc. are altogether the same except having not formed the lobe 509 which is the part where earth capacity becomes large to the example 1 of drawing 5 at the leading-about wiring 508 about the layout on the piezo-electric substrate 501, but having taken about the leading-about wiring 508, and having set it as axial symmetry to wiring 507 and the virtual shaft A. The phase unbalance of the example 1 of a comparison which changed the layout on the piezo-electric substrate 501 into nothing [lobe] is also doubled, and it is shown in drawing 8.

[0051]

The passband of the filter for DCS reception is 1805MHz - 1880MHz. In the example 1, whenever [phase equilibrium] is improved about about 10 degrees with about 12 maxes to gaps of the phase unbalance of this passband within the limits being about 22 maxes in the example 1 of a comparison according to drawing 8. This is adjusting so that the earth capacity of the balanced signal terminal 413 may become large, and is the effectiveness that the phase shift between the balanced signal terminal 412 and the balanced signal terminal 413 was amended.

[0052]

In the example 1, the lobe 509 which is the part where earth capacity becomes large was formed in the leading-about wiring 508. Next, with this, the lobe 515 as a part where it takes about like drawing 10 conversely, and earth capacity becomes large at wiring 507 was formed,

and phase unbalance when about 0.16pF of earth capacity of the balanced signal terminal 412 becomes large was investigated. The phase unbalance in the case of drawing 10 is shown in drawing 11 . As a comparison, the result in the case of the example 1 of a comparison shown in drawing 9 is also shown according to drawing 11 .

[0053]

When it is made for the earth capacity of the balanced signal terminal 412 to become large, phase unbalance is getting worse rather than the example 1 of a comparison conversely. Of which balanced signal terminal earth capacity is enlarged should just determine by the existence of the non-electric-field field where the method of a list, i.e., the signal electrodes, and ground electrodes of the electrode finger which adjoins each other mutually of IDT 402-404 adjoins each other mutually.

[0054]

Each electrode finger [in / in the case of an example 1 / IDT404] with which IDT 403 and 405 is adjoined is each signal electrode of each comb mold electrodes 416 and 417. The electrode finger in IDT405 which adjoins the comb mold electrode 417 which is made leading-about wiring with which earth capacity becomes large on the other hand, and which is connected to the electrode pad 504 which adjoins IDT404 is a signal electrode, and forms the signal electrode and nothing (smallness) electric-field field which are the outermost electrode finger of the comb mold electrode 417 which meets. The electrode finger in IDT403 which, on the other hand, adjoins the comb mold electrode 416 connected to the electrode pad 503 which adjoins IDT404 is a ground electrode, and forms an electric-field field with much signal electrode which is the outermost electrode finger of the comb mold electrode 416 which meets, and thing [field / above-mentioned / nothing (smallness) electric-field / electric field].

[0055]

in the case of such a list of an electrode finger, phase unbalance is improvable by setting up by the lobe 509 so that it may become large relatively from the balanced signal terminal 412 by which the earth capacity of the balanced signal terminal 413 connected to the comb mold electrode 417 which has a non-electric-field field near the outermost electrode finger (or the above-mentioned outermost electrode finger -- facing) like an example 1 is connected to the comb mold electrode 416

[0056]

Next, it investigated like drawing 12 about the case where each electrode finger which adjoins each IDT 703 and 705 of IDT704, respectively is a neutral point electrode (a float electrode or a ground

electrode is sufficient). The phase unbalance in the layout which shows the phase unbalance in the layout on the piezo-electric substrate 501 shown in drawing 13 at drawing 10 in the electrode configuration of drawing 12 (example of a complete-change form of an example 1), and is shown in drawing 14 at drawing 5 in the electrode configuration of drawing 12 (example 3 of a comparison) is shown. The phase unbalance in the layout (nothing [lobe]) shown in drawing 9 in the electrode configuration of drawing 12 as an example 2 of a comparison is also shown as an example 2 of a comparison according to drawing 13 and drawing 14 , respectively. Drawing 13 and drawing 14 are the results at the time of adjusting, respectively so that the earth capacity of about 0.02pF may go into the part of a lobe 515 and a lobe 509.

[0057]

In the case of the list of the electrode finger shown in drawing 12 , it turns out that phase unbalance is improved like the layout shown in drawing 10 by making it become large relatively from the balanced signal terminal 713 by which the earth capacity of the balanced signal terminal 712 connected to the comb mold electrode 716 is connected to the comb mold electrode 717.

[0058]

Next, in the electrode configuration of drawing 12 , the phase unbalance at the time of adding the delay line and an inductance component to unbalance to each balanced signal terminal at a serial, respectively was investigated, respectively.

[0059]

The configuration (other modifications of an example 1) which added the delay line 720 as a reactance component 120 shown in drawing 1 to drawing 15 to the balanced signal terminal 712 connected to the comb mold electrode 716 is shown, and the configuration (modification of further others of an example 1) which added the inductance component 722 as a reactance component 120 shown in drawing 1 to drawing 16 is shown.

[0060]

Drawing 15 and the phase unbalance of the case in each configuration of drawing 16 are shown in drawing 17 and drawing 18 . As a comparison, the layout of drawing 9 in the configuration of drawing 12 also shows the phase unbalance when having not added a delay-line or inductance component, either as an example 2 of a comparison respectively according to drawing 17 and drawing 18 .

[0061]

Although the concrete formation approach of the above-mentioned delay line 720 or the inductance component 722 is omitted, it is possible to

form the delay line which lengthened leading-about wiring a piezo-electric substrate top and in a package, for example, or to prepare the inductance component by the microstrip line.

[0062]

Moreover, as long as it is possible, as shown, for example in drawing 31 (a) and drawing 31 (b), respectively, you may carry out external to the location of outsides other than the interior of a package. In drawing 31 (a), the delay line and the circuit 655 used as an inductance component (reactance component) are established in the boundary part of the side-attachment-wall section 652 and a bottom plate 651, and it sets to drawing 31 (b). On a bottom plate 651, it may connect with a laminate 657 and a laminate 657 through a beer hall 658 and a beer hall 658 in the thickness direction, and the delay line formed between the bottom plate 651 and the laminate 657 and the circuit 659 used as an inductance component may be formed.

[0063]

When any of the delay line 720 and the inductance component 722 are inserted so that clearly from drawing 17 and drawing 18 , it turns out that phase unbalance has improved to the example 2 of a comparison. In addition, what is necessary is just to add the delay line 720 or the inductance component 722 to the balanced signal terminal 413 in the electrode configuration of drawing 4 conversely.

[0064]

As explained above, it has the vertical joint resonator mold surface acoustic wave filter which has three IDT(s) formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate in the example 1. In the surface acoustic wave equipment which gave balanced - unbalance conversion function by dividing into two IDT located in the center among three IDT(s) in the propagation direction of a surface acoustic wave, and reversing the polarity of IDT on either side The phase unbalance of surface acoustic wave equipment is improvable by making unsymmetrical between each two balanced signal terminals earth capacity, the inductance component linked to a serial, and the reactance component that is at least one of the delay lines.

[0065]

Although how to bring the signal electrode on the piezo-electric substrate 501 close to a ground electrode was shown as it considered as the approach of enlarging earth capacity in the example 1 and was shown in drawing 5 , this may form capacity 517 with a comb mold electrode like drawing 19 . Moreover, leading-about wiring in a package 640 may be adjusted.

[0066]

Moreover, in order to lose an excessive unbalance component, it was made for the layout on the piezo-electric substrate 501 and package 640 grade to become the same to a balanced signal terminal in the example 1 except adding earth capacity, an inductance component, and the delay line asymmetrically. Therefore, although the example (refer to drawing 6) in case the number of each electrode terminals 641-645 by the side of rear-face 640a of a package 640 is five was shown, as long as this invention is a package made into axial symmetry to the virtual shaft A lengthened at right angles to the propagation direction of a surface acoustic wave such centering on not only a package but centering on the center IDT divided into two, it may use what kind of package.

[0067]

For example, in the case of the package 800 which has six electrode terminals 801-806 like drawing 20 , it can consider as axial symmetry to the virtual shaft A by using an electrode terminal 801 as an unbalance signal terminal, using each electrode terminals 802 and 803 as a balanced signal terminal, and using each electrode terminals 804-806 as a grounding terminal.

[0068]

In that case, the pattern layout on the piezo-electric substrate 501 like drawing 21 The propagation direction of a surface acoustic wave should be met in the direction of a long side of the piezo-electric substrate 501. To an electrode terminal 801, the electrode pad 902 for the electrode pad 901 on the piezo-electric substrate 501 to an electrode terminal 802 The piezo-electric substrate 501 top can also be easily made into axial symmetry to the virtual shaft A by connecting the electrode pad 903 to an electrode terminal 803, and connecting each electrode pads 904-906 to each electrode terminals 804-806 used as a grounding terminal, respectively.

[0069]

Moreover, although surface acoustic wave equipment was produced like drawing 7 in the example 1 by the approach of taking the flow of a package and a piezo-electric substrate by the face down method of construction, it is satisfactory even if this is a wire bond method of construction.

[0070]

Moreover, join the piezo-electric substrate 1002 by the flip chip method of construction on the set substrate 1001 not only like the configuration of drawing 7 but like drawing 22 as a configuration produced by the face down method of construction, and resin 1003 is

covered and closed on it. As shown in the configuration cut per 1 package by dicing, and drawing 2323 , similarly join the piezo-electric substrate 1102 by the flip chip method of construction on the set substrate 1101, and the sheet-like resin material 1103 is covered and closed on it. Surface acoustic wave equipment may be produced with the configuration cut per 1 package by dicing.

[0071]

Although the example 1 showed the configuration which carried out series connection of the surface acoustic wave resonator to the vertical joint resonator mold surface acoustic wave filter which has three IDT(s), also in the configuration to which the surface acoustic wave resonator is not connected, and the configuration by which parallel connection was carried out further, it is clear that the same effectiveness is acquired. Moreover, you may be the configuration of the vertical joint resonator mold of 5IDT which prepared IDT in the both sides of three IDT(s) further like drawing 24 .

[0072]

Moreover, even if it has given weighting like drawing 25 to the electrode finger 130 of the neighborhood where IDT adjoins each other, the effectiveness of this invention is acquired. In the configuration of drawing 25 , unbalance is improved further. As an example of weighting, although serial weighting is used in drawing 25 , this may be infanticide weighting, decussation width-of-face weighting, and duty weighting.

[0073]

Moreover, in this invention, you may be the configuration which carried out cascade connection of other vertical joint resonator mold surface acoustic wave filters 201 to the vertical joint resonator mold surface acoustic wave filter 101 like drawing 2 . As for IDT203 located in the center section of the vertical joint resonator mold surface acoustic wave filter 201, it is desirable in that case for the total electrode finger number to be even.

[0074]

Moreover, it is desirable to adjust each IDT 102 and 104 and each sense of IDT 202 and 204 so that the phases of the signal which transmits each signal lines 205 and 206 which have connected the vertical joint resonator mold surface acoustic wave filter 101 and the vertical joint resonator mold surface acoustic wave filter 201 of each other may differ about 180 degrees. The surface acoustic wave equipment which excelled [make / it / the above-mentioned configuration] in unbalance further is obtained.

[0075]

The case where it mounts in the package which has six electrode terminals shown in drawing 26 and drawing 27 at drawing 20 again about the case where it mounts in the package which has each five electrode terminals which show the example of the layout on the piezo-electric substrate 501 in the case of using the electrode configuration of drawing 2 to drawing 6 is shown in drawing 28 and drawing 29 R> 9.

[0076]

Each electrode pads 1201, 1301, 1401, and 1501 become the configuration that connect an unbalance signal terminal and each electrode pads 1202, 1203, 1302, 1303, 1402, 1403, 1502, and 1503 to a balanced signal terminal, and they connect the remainder to a grounding terminal, in that case.

[0077]

In the example 1, although 40 °5-degreeYcutX propagation LiTaO₃ substrate was used as a piezo-electric substrate 501, as for this invention, the same effectiveness is acquired not only with this piezo-electric substrate 501 but with piezo-electric substrates, such as the 64 degrees - 72 degreeYcutX propagation LiNbO₃ and the 41-degreeYcutX propagation LiNbO₃, as the principle from which effectiveness is acquired also shows.

[0078]

Next, the communication device using the surface acoustic wave equipment of this invention used as the above-mentioned example 1 concerning this invention and either of each of that modification, or the combination of those descriptions is explained based on drawing 30 .

[0079]

As shown in drawing 30 , as a receiver side (Rx side) which receives, the above-mentioned communication device 600 is equipped with an antenna 601, the antenna common section / RFTop filter 602, amplifier 603, Rx interstage filter 604, a mixer 605, the 1stIF filter 606, a mixer 607, the 2ndIF filter 608, the 1st+2nd local synthesizer 611, TCXO (temperature compensated crystal oscillator (temperature-compensated crystal oscillator))612, a divider 613, and the local filter 614, and is constituted. As double lines showed, in order to secure balance nature from Rx interstage filter 604 to drawing 30 to a mixer 605, transmitting by each balanced signal is desirable.

[0080]

Moreover, as a transceiver side (Tx side) which transmits, it has the TxIF filter 621, a mixer 622, Tx interstage filter 623, amplifier 624, a coupler 625, an isolator 626, and APC (automatic power control)627 (APC),

and the above-mentioned communication device 600 is constituted while sharing the above-mentioned antenna 601, and the above-mentioned above-mentioned antenna common section / RFTop filter 602.

[0081]

And the surface acoustic wave equipment of this example mentioned above can use for the above-mentioned Rx interstage filter 604, the 1stIF filter 606, the TxIF filter 621, Tx interstage filter 623, and the antenna common section / RFTop filter 602 suitably.

[0082]

The surface acoustic wave equipment concerning this invention is equipped with an unbalance-balance conversion function with a filtering function, and, moreover, the amplitude characteristic and the phase characteristic between each balanced signal have the outstanding property of being near, by the ideal. Therefore, the communication device of this invention which has the above-mentioned surface acoustic wave equipment can be improving the transmission characteristic while being able to reduce the number of component parts and being able to miniaturize by having used the compound-ized above-mentioned surface acoustic wave equipment.

[0083]

[Effect of the Invention]

As explained above, the surface acoustic wave equipment of this invention It is the vertical joint resonator mold surface acoustic wave filter which has three IDT(s) formed along the propagation direction of a surface acoustic wave on the piezo-electric substrate. Divide into two IDT located in the center among three IDT(s) of said vertical joint resonator mold surface acoustic wave filter in the propagation direction of a surface acoustic wave at the abbreviation symmetry, and each is connected to a balanced signal terminal. In the surface acoustic wave equipment which gave balanced - unbalance conversion function by connecting to an unbalance signal terminal IDT of the right and left which reversed the polarity It is the configuration that the reactance component is connected [at either of said each balanced signal terminal] to the package and the package external at least one the piezo-electric substrate top.

[0084]

So, the above-mentioned configuration does the effectiveness that the unbalance between each balanced signal terminal is improvable, by connecting a reactance component to either of each balanced signal terminal.

[Brief Description of the Drawings]

[Drawing 1] It is the block diagram of the surface acoustic wave equipment of this invention.

[Drawing 2] It is the block diagram of the example of the complete-change form of the above-mentioned surface acoustic wave equipment (cascade connection).

[Drawing 3] It is the block diagram of conventional surface acoustic wave equipment.

[Drawing 4] It is the block diagram showing the electrode configuration of the surface acoustic wave equipment concerning the example 1 of this invention.

[Drawing 5] It is the top view showing the layout on the piezo-electric substrate in the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 6] It is the top view showing arrangement of each terminal by the side of the rear face of the package which contained the surface acoustic wave equipment of the above-mentioned example 1, respectively with the perspective drawing from the top-face (opposed face on the back) side of a package.

[Drawing 7] It is the sectional view of the package which contained the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 8] It is the graph which shows the phase unbalance in each configuration of the above-mentioned example 1 and the example 1 of a comparison, respectively.

[Drawing 9] It is the top view showing the layout of the surface acoustic wave equipment of the above-mentioned example 1 of a comparison.

[Drawing 10] It is the top view showing the layout of the surface acoustic wave equipment as an example 2 of a comparison.

[Drawing 11] It is the graph which shows the phase unbalance in the configuration (example 2 of a comparison) shown in drawing 10, and each configuration of the above-mentioned example 1 of a comparison, respectively.

[Drawing 12] It is the block diagram showing the electrode configuration about the surface acoustic wave equipment as an example of a complete-change form of the above-mentioned example 1.

[Drawing 13] When the electrode configuration of drawing 12 is constituted from a layout on the piezo-electric substrate of drawing 10, it is the graph which shows the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 14] When the electrode configuration of drawing 12 is constituted from a layout on the piezo-electric substrate of drawing 5, it is the graph which shows the frequency-phase unbalance of the example

2 of a comparison, respectively.

[Drawing 15] It is the block diagram showing the surface acoustic wave equipment of other modifications of the above-mentioned example 1.

[Drawing 16] It is the block diagram showing the surface acoustic wave equipment of the modification of further others of the above-mentioned example 1.

[Drawing 17] It is the graph which shows the configuration of drawing 15 , and the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 18] It is the graph which shows the configuration of drawing 16 , and the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 19] It is the block diagram showing the surface acoustic wave equipment of the modification of further others of the above-mentioned example 1.

[Drawing 20] It is the top view showing other examples about arrangement of each electrode terminal in the package of the above-mentioned example 1.

[Drawing 21] It is the block diagram showing the modification of further others of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 22] It is the sectional view showing the 1 manufacture process of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 23] It is the sectional view showing other manufacture processes of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 24] It is the block diagram showing the modification of further others of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 25] It is the block diagram showing the modification of further others of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 26] It is the top view showing an example of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face which shows the electrode configuration shown in said drawing 2 to drawing 6 .

[Drawing 27] It is the top view showing the electrode configuration shown in above-mentioned drawing 2 in drawing 6 showing other examples of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face.

[Drawing 28] It is the top view showing an example of the layout on a

piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face which shows the electrode configuration shown in said drawing 2 to drawing 20 .

[Drawing 29] It is the top view showing the electrode configuration shown in said drawing 2 in drawing 20 showing other examples of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face.

[Drawing 30] It is the important section block diagram of the communication device concerning this invention.

[Drawing 31] It is the sectional view of the above-mentioned package when external [of the reactance component or the delay line at the time of containing the surface acoustic wave equipment of the above-mentioned example 1 in a package] is carried out to a package. (a) It is the example by which the circuit as the above-mentioned reactance component or the delay line was formed between a bottom plate and the side-attachment-wall section, and (b) is the example by which the above-mentioned reactance component or the delay line was formed as a circuit in the multilayer board which formed the laminate further on the bottom plate.

[Description of Notations]

101 Vertical Joint Resonator Mold Surface Acoustic Wave Filter

102, 103, 104 IDT (comb mold polar zone)

107 Unbalance Signal Terminal

108 109 Balanced signal terminal

120 Reactance Component

501 Piezo-electric Substrate

[Translation done.]

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3. In the drawings, any words are not translated.

DESCRIPTION OF DRAWINGS

[Brief Description of the Drawings]

[Drawing 1] It is the block diagram of the surface acoustic wave equipment of this invention.

[Drawing 2] It is the block diagram of the example of the complete-change form of the above-mentioned surface acoustic wave equipment (cascade connection).

[Drawing 3] It is the block diagram of conventional surface acoustic wave equipment.

[Drawing 4] It is the block diagram showing the electrode configuration of the surface acoustic wave equipment concerning the example 1 of this invention.

[Drawing 5] It is the top view showing the layout on the piezo-electric substrate in the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 6] It is the top view showing arrangement of each terminal by the side of the rear face of the package which contained the surface acoustic wave equipment of the above-mentioned example 1, respectively with the perspective drawing from the top-face (opposed face on the back) side of a package.

[Drawing 7] It is the sectional view of the package which contained the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 8] It is the graph which shows the phase unbalance in each configuration of the above-mentioned example 1 and the example 1 of a comparison, respectively.

[Drawing 9] It is the top view showing the layout of the surface acoustic wave equipment of the above-mentioned example 1 of a comparison.

[Drawing 10] It is the top view showing the layout of the surface acoustic wave equipment as an example 2 of a comparison.

[Drawing 11] It is the graph which shows the phase unbalance in the configuration (example 2 of a comparison) shown in drawing 10, and each configuration of the above-mentioned example 1 of a comparison, respectively.

[Drawing 12] It is the block diagram showing the electrode configuration about the surface acoustic wave equipment as an example of a complete-change form of the above-mentioned example 1.

[Drawing 13] When the electrode configuration of drawing 12 is constituted from a layout on the piezo-electric substrate of drawing 10, it is the graph which shows the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 14] When the electrode configuration of drawing 12 is constituted from a layout on the piezo-electric substrate of drawing 5,

it is the graph which shows the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 15] It is the block diagram showing the surface acoustic wave equipment of other modifications of the above-mentioned example 1.

[Drawing 16] It is the block diagram showing the surface acoustic wave equipment of the modification of further others of the above-mentioned example 1.

[Drawing 17] It is the graph which shows the configuration of drawing 15 , and the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 18] It is the graph which shows the configuration of drawing 16 , and the frequency-phase unbalance of the example 2 of a comparison, respectively.

[Drawing 19] It is the block diagram showing the surface acoustic wave equipment of the modification of further others of the above-mentioned example 1.

[Drawing 20] It is the top view showing other examples about arrangement of each electrode terminal in the package of the above-mentioned example 1.

[Drawing 21] It is the block diagram showing the modification of further others of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 22] It is the sectional view showing the 1 manufacture process of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 23] It is the sectional view showing other manufacture processes of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 24] It is the block diagram showing the modification of further others of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 25] It is the block diagram showing the modification of further others of the surface acoustic wave equipment of the above-mentioned example 1.

[Drawing 26] It is the top view showing an example of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face which shows the electrode configuration shown in said drawing 2 to drawing 6 .

[Drawing 27] It is the top view showing the electrode configuration shown in above-mentioned drawing 2 in drawing 6 showing other examples of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face.

[Drawing 28] It is the top view showing an example of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face which shows the electrode configuration shown in said drawing 2 to drawing 20 .

[Drawing 29] It is the top view showing the electrode configuration shown in said drawing 2 in drawing 20 showing other examples of the layout on a piezo-electric substrate at the time of mounting in the package which has each electrode terminal by the side of a rear face.

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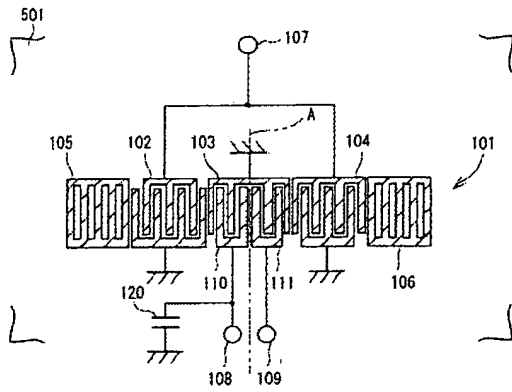
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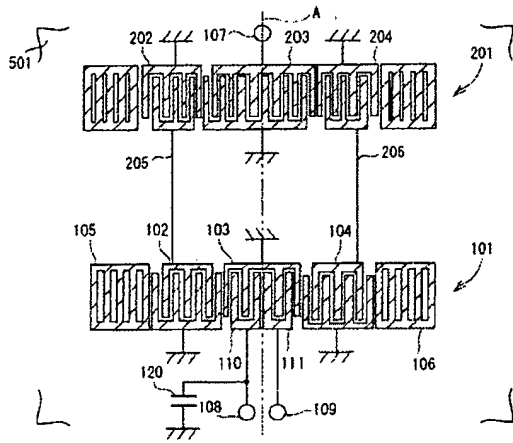
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DRAWINGS

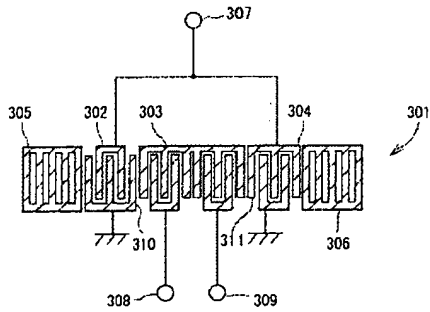
[Drawing 1]



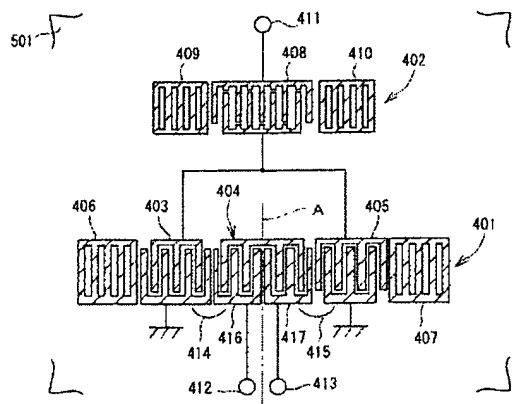
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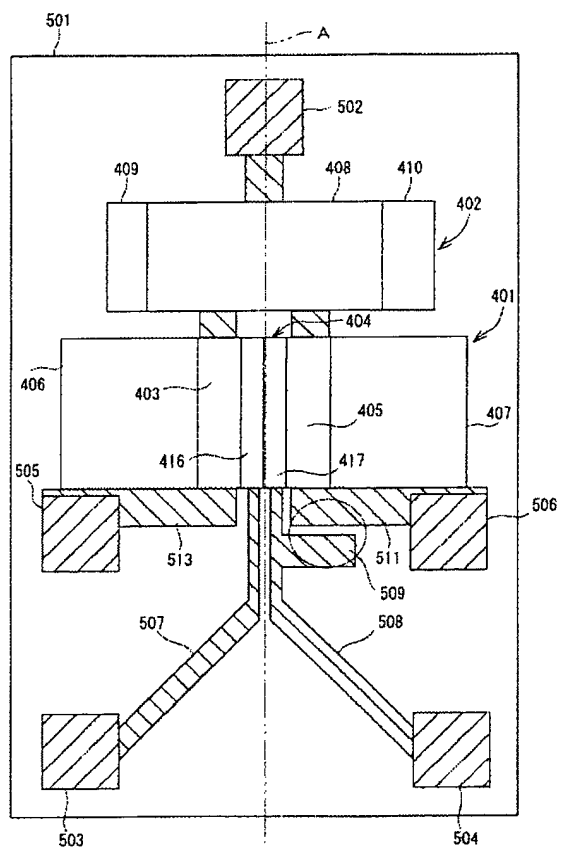
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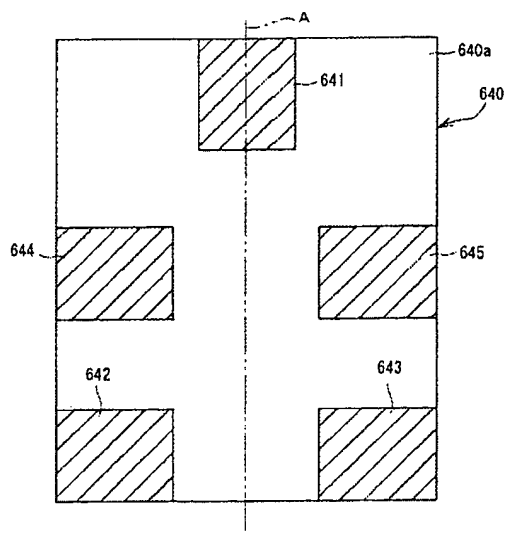
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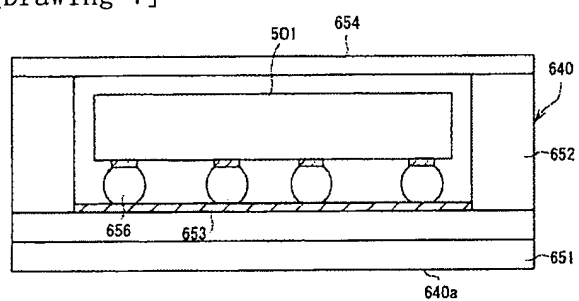
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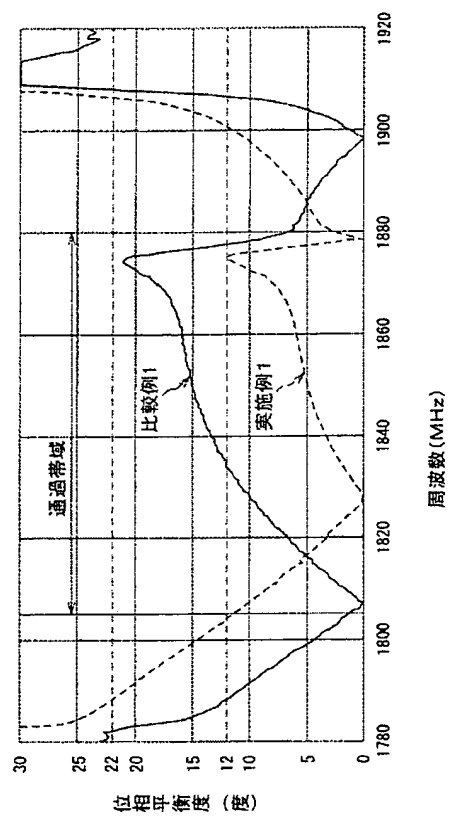
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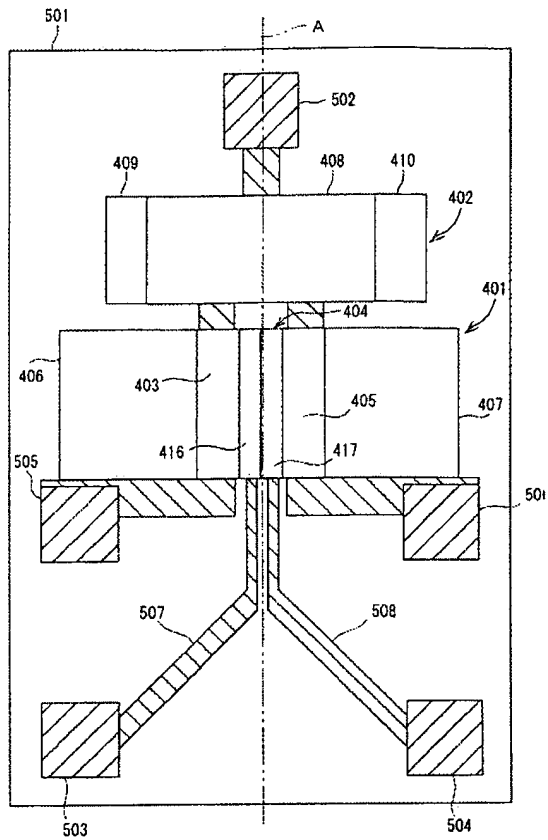
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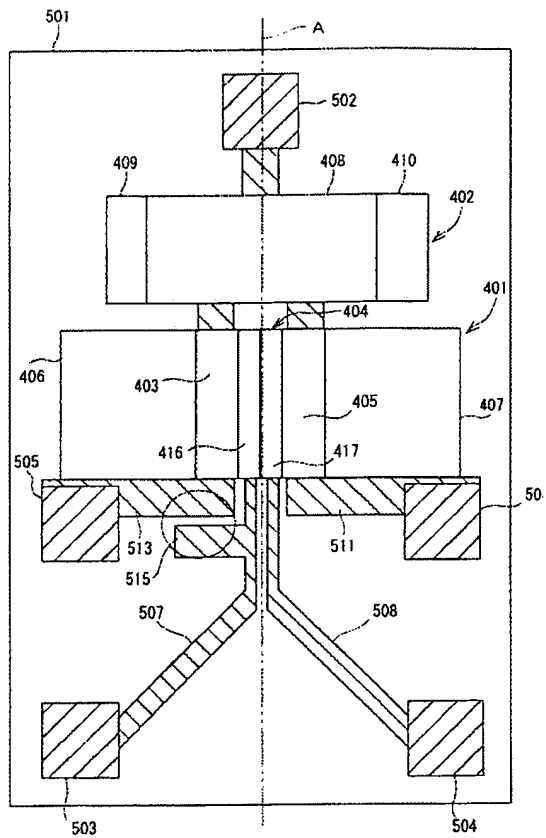
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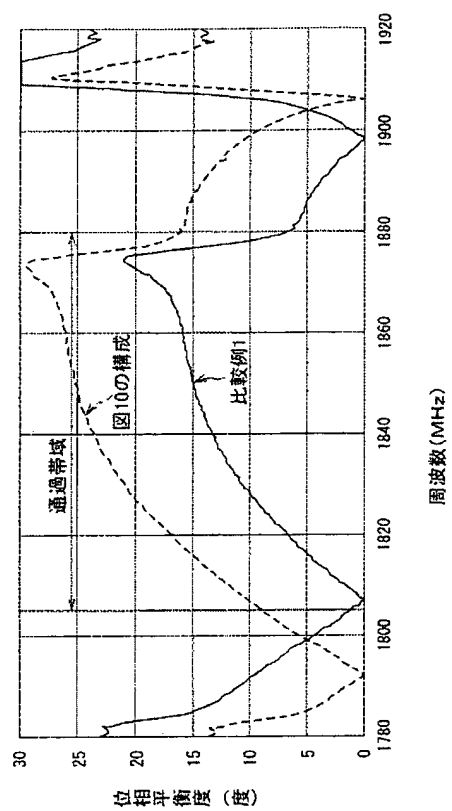
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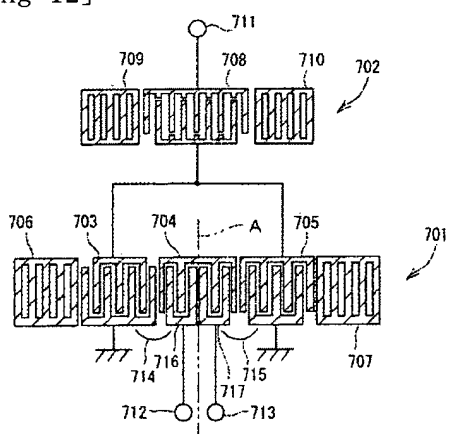
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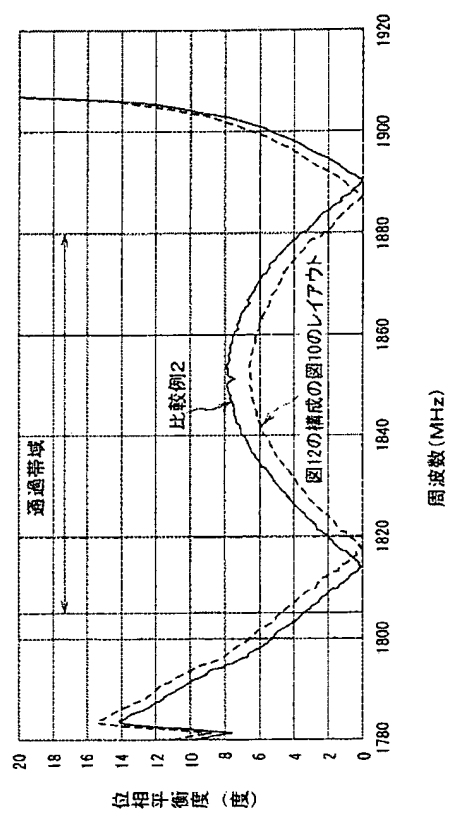
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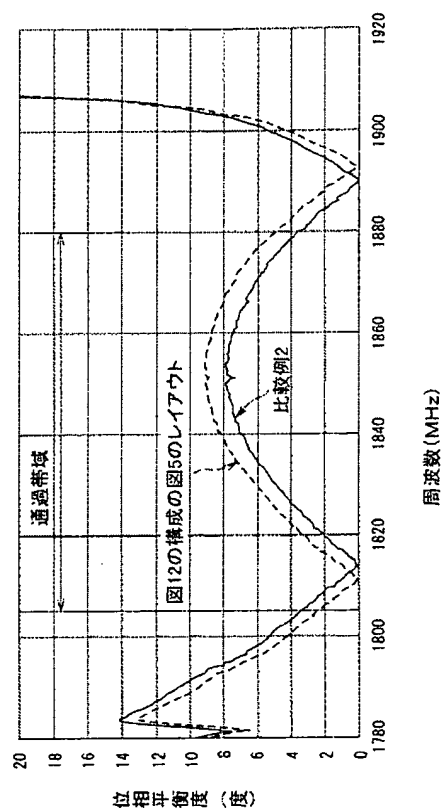
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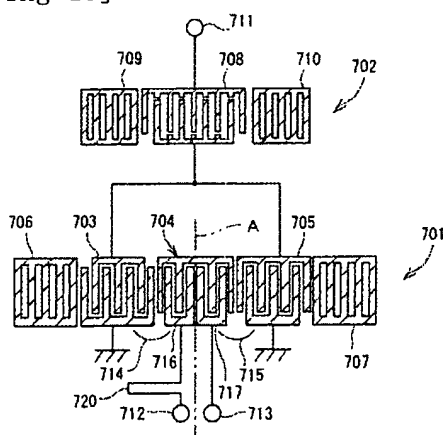
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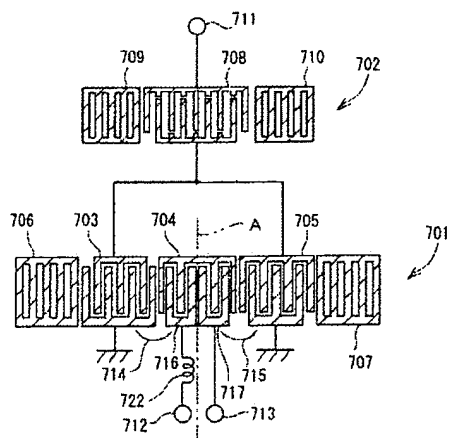
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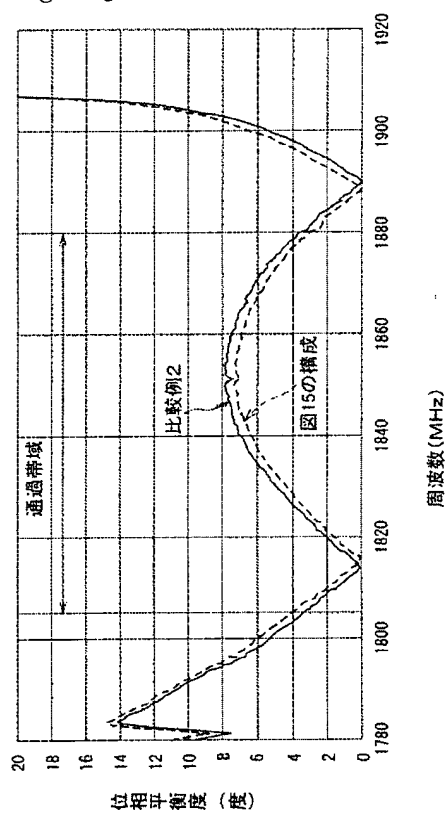
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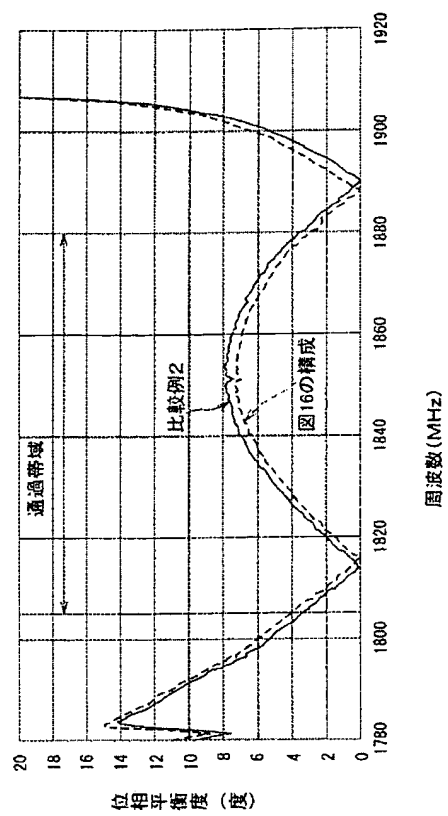
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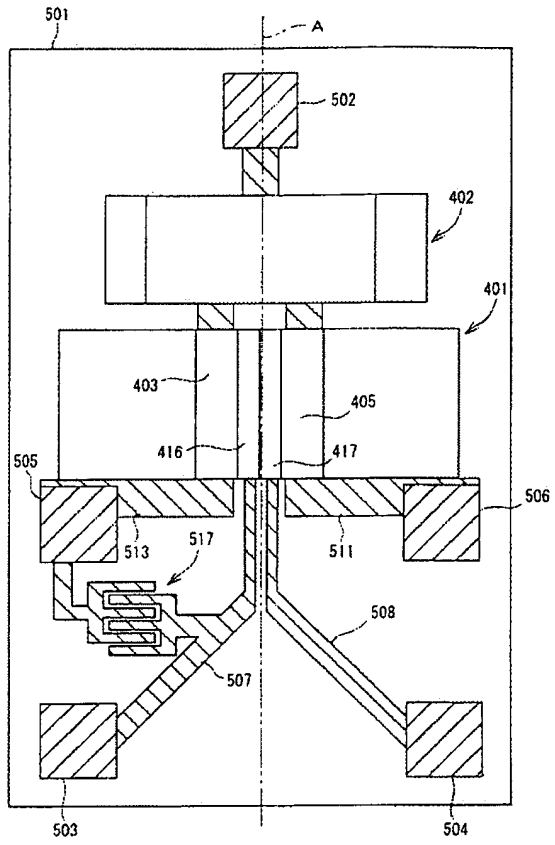
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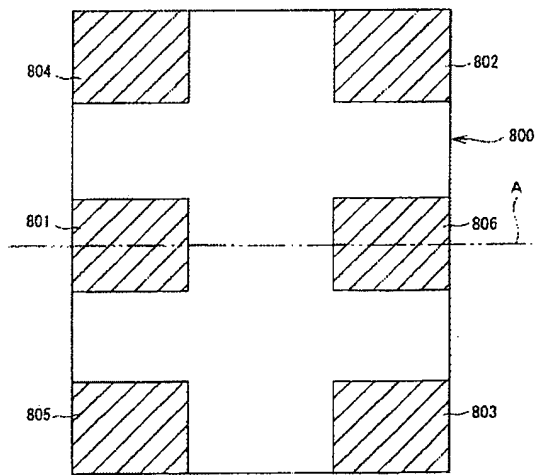
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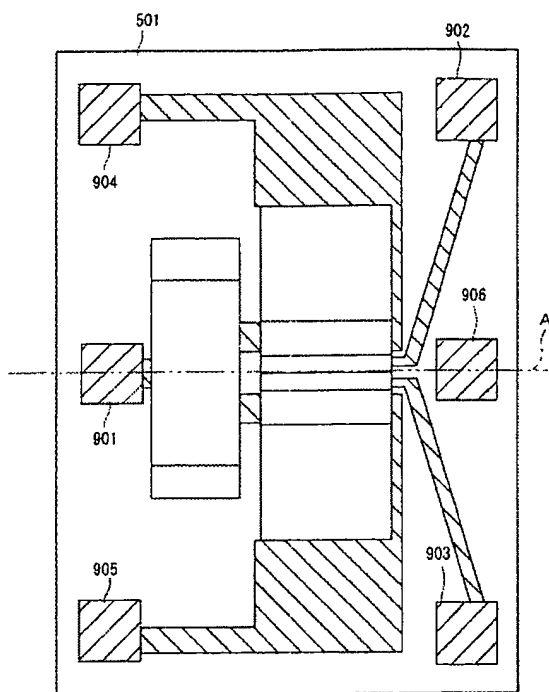
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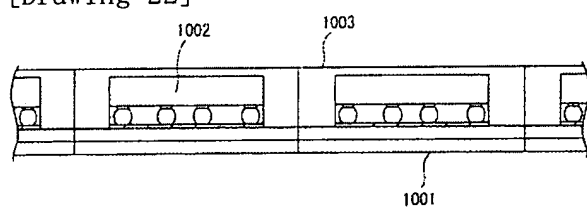
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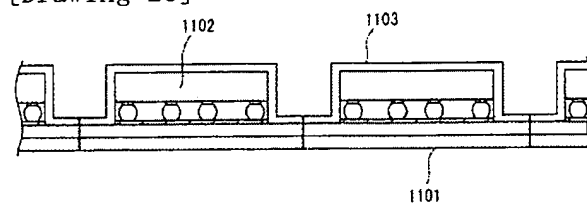
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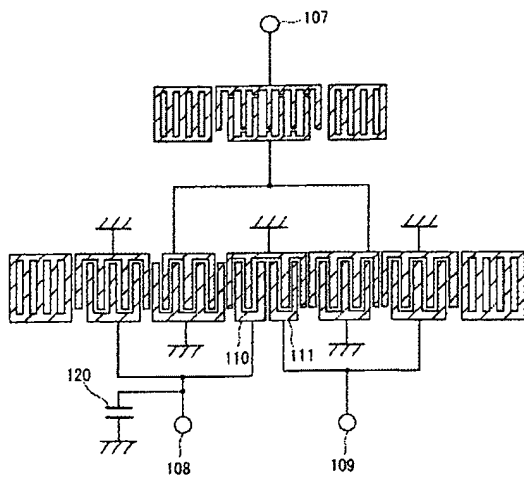
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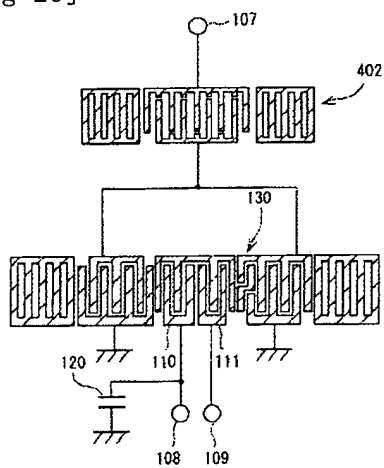
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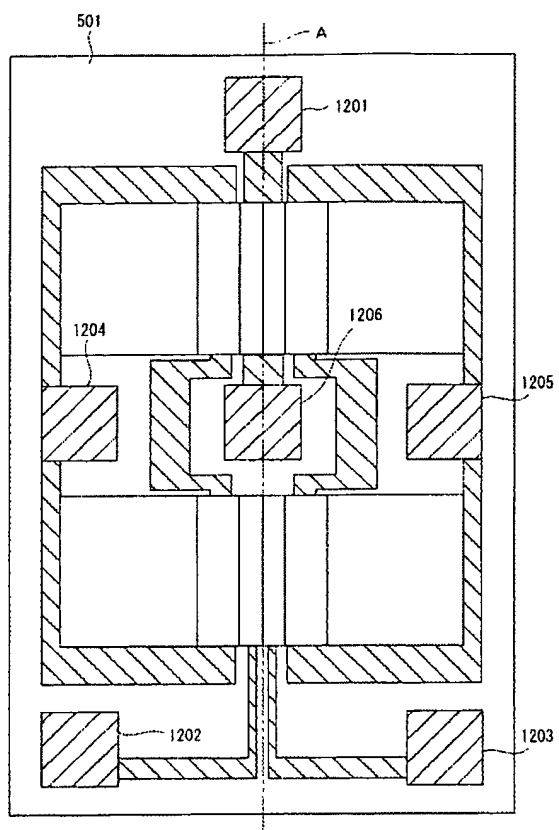
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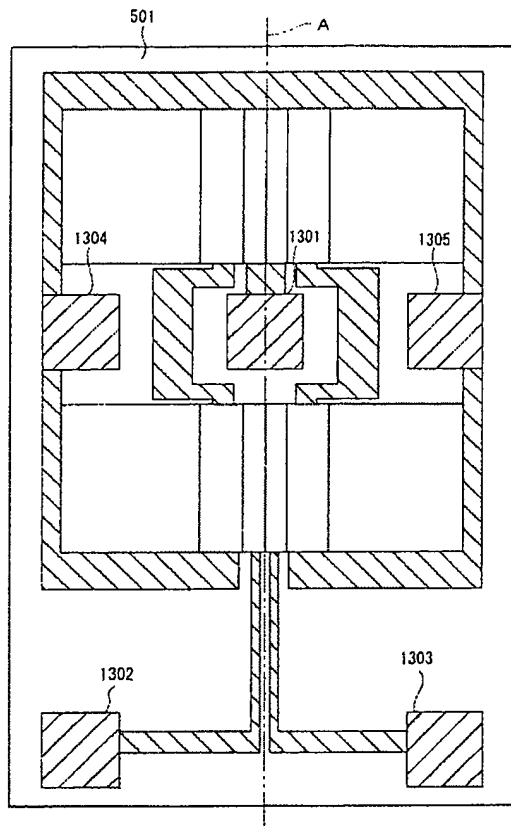
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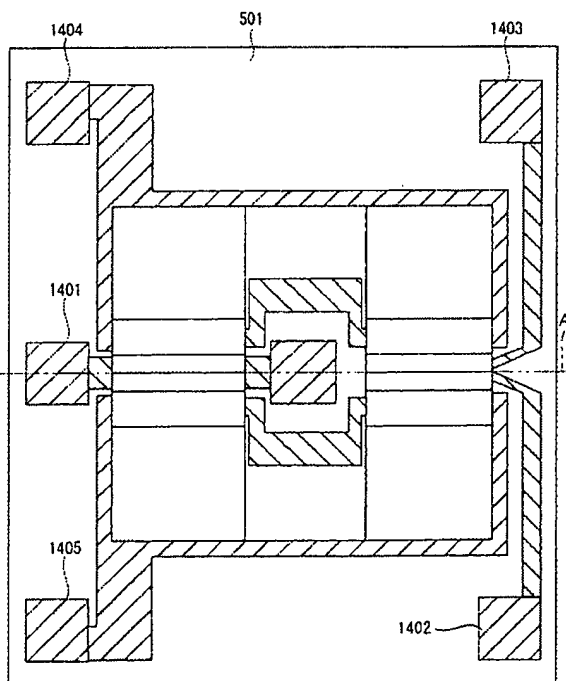
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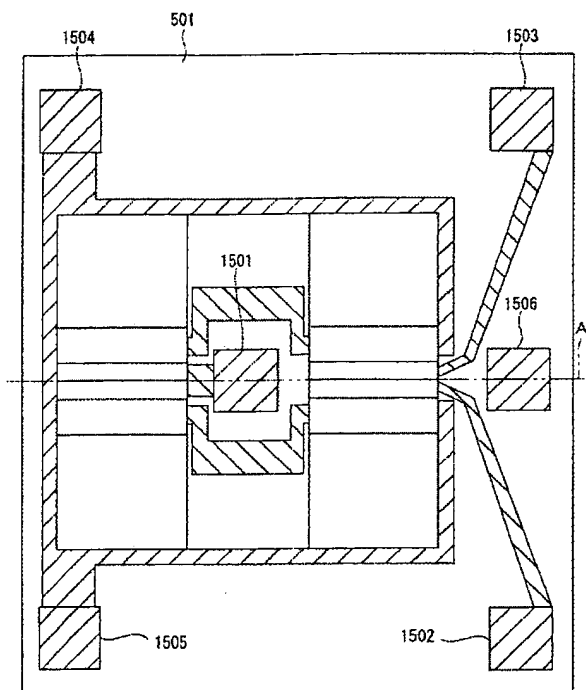
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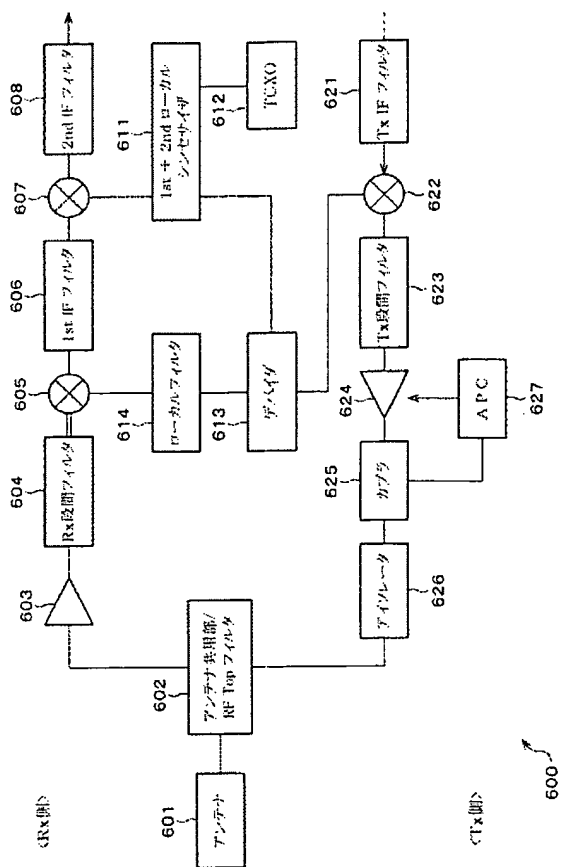
[Drawing 28]

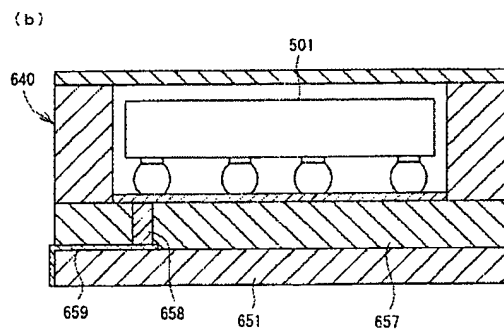
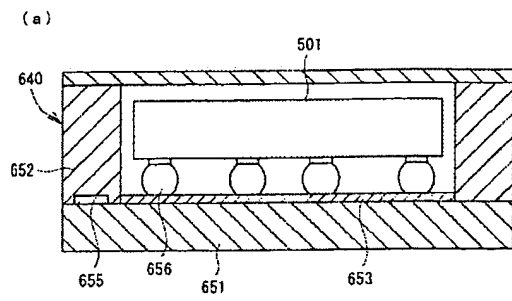


[Drawing 29]



[Drawing 30]





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